

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Attorney Docket No.: 105192.01

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Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

BOX PATENT APPLICATION
CONTINUING APPLICATION TRANSMITTAL
RULE 1.53(b)

Sir:

Transmitted herewith for filing under 37 C.F.R. §1.53(b) is a

Continuation Divisional Continuation-in-Part

application of prior pending Application No. 09/234,969, filed January 21, 1999,

For (Title): PROJECTION OPTICAL SYSTEM AND EXPOSURE APPARATUS AND METHOD

By (Inventors): Koji SHIGEMATSU

1. A Declaration and Power of Attorney is attached. The attached Declaration and Power of Attorney is:

a. A copy of the Declaration and Power of Attorney from the parent application. (Used with the same or fewer inventors and (a) a copy of the prior application or (b) a revised, reformatted or edited version of the prior application that does not contain new matter.)

b. A new Declaration and Power of Attorney. (Used with the same, fewer or additional inventors and (a) a copy of the prior application, (b) a revised, reformatted or edited version of the prior application that does not contain new matter, or (c) a new specification.)

2. The filing fee is calculated below:

**CLAIMS IN THE APPLICATION AFTER ENTRY OF
ANY PRELIMINARY AMENDMENT NOTED BELOW**

FOR:	NO. FILED	NO. EXTRA
BASIC FEE		
TOTAL CLAIMS	6 - 20	= 0
INDEP CLAIMS	5 - 3	= 2
<input type="checkbox"/> MULTIPLE DEPENDENT CLAIMS PRESENTED		

* If the difference is less than zero, enter "0".

SMALL ENTITY

RATE	FEES
	\$ 355
x 9 =	\$
x 40 =	\$
+135 =	\$
TOTAL	\$

**OTHER THAN A
SMALL ENTITY**

RATE	FEES
	\$ 710
x 18	\$ 0
x 80	\$ 160
+270	\$ 0
TOTAL	\$ 870

3. Check No. 114098 in the amount of \$870.00 to cover the filing fee is attached. The Director is hereby authorized to charge any other fees that may be required to complete this filing, or to credit any overpayment, to Deposit Account No. 15-0461. Two duplicate copies of this sheet are attached.

4. Cancel claims _____ of the application before calculating the filing fee. At least one independent claim is retained for filing purposes.

DEPOSIT ACCOUNT USE
AUTHORIZATION
Please grant any extension
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Deposit Account No. 15-0461

5. Amend the specification by inserting before the first line the sentence:
--This is a Continuation Division Continuation-in-Part of Application No. 09/234,969 filed January 21, 1999. The entire disclosure of the prior application(s) is hereby incorporated by reference herein in its entirety.--

6. Formal drawings (Figs. 1-10) are attached.

7. Priority of foreign application No. 10-024043 filed January 22, 1998 in Japan is claimed under 35 U.S.C. §119 and/or §365(b).
 The certified copy was filed in prior Application No. 09/234,969 on February 8, 1999.
 A certified copy of the above foreign application(s) is filed herewith.

8. Priority of U.S. Provisional Application(s) No. _____ filed _____ is claimed under 35 U.S.C. §119.
 Amend the specification by inserting before the first line the sentence:
--This nonprovisional application claims the benefit of U.S. Provisional Application(s) No. _____ filed _____.--

9. The prior application is assigned of record to NIKON CORPORATION recorded at Reel 9732, Frame 0604.

10. This application is filed by fewer than all the inventors named in the prior application (37 C.F.R. §1.53(b)(1)). Delete the following inventor(s) named in the prior application:

11. A Preliminary Amendment is attached. Claims added by this Amendment are properly numbered consecutively beginning with the number next following the highest numbered claim in the application.

12. An Information Disclosure Statement is attached.

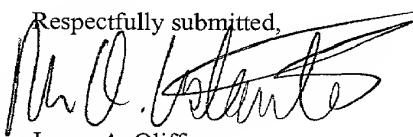
13. Small entity status:
 a. Entitlement to small entity status is asserted.
 b. Small entity status is no longer claimed.

14. Other: _____

15. The power of attorney in the application is to James A. Oliff, Registration No. 27,075, William P. Berridge, Registration No. 30,024, Kirk M. Hudson, Registration No. 27,562, Thomas J. Pardini, Registration No. 30,411, Edward P. Walker, Registration No. 31,450, Robert A. Miller, Registration No. 32,771, Mario A. Costantino, Registration No. 33,565, and/or Stephen J. Roe, Registration No. 34,463.
 a. The power appears in the attached Declaration and Power of Attorney.
 b. Since the power does not appear in the attached Declaration and Power of Attorney, a substitute Power of Attorney is also attached.

16. Address all future communications to:

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Respectfully submitted,

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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Koji SHIGEMATSU

Group Art Unit: Not yet Assigned

Application No.: Rule 53(b) Division of Application Examiner: Not yet Assigned
No. 09/234,969

Filed: November 28, 2000

Docket No.: 105192.01

For: PROJECTION OPTICAL SYSTEM AND EXPOSURE APPARATUS AND METHOD

PRELIMINARY AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

Prior to initial examination on the merits, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 1-15, 19-30 and 33-37 without prejudice or disclaimer.

Please amend claims 16, 17, 31, 32 and 38 as follows:

16. (Amended) A method of patterning a photosensitive workpiece with a pattern present on a reticle, the method comprising the steps of:

- a) illuminating the reticle;
- b) projecting light from said reticle with [the] a projection optical system,

[as set forth in claim 1] said projection optical system including, along an optical axis:

i) a first lens group having positive refractive power,

ii) a second lens group having negative refractive power,

iii) a third lens group having positive refractive power,
iv) a fourth lens group having negative refractive power and a first
aspherical surface,
v) a fifth lens group having positive refractive power and an aperture
stop,
vi) wherein the projection optical system is designed such that paraxial
rays traveling parallel to the optical axis imagewise to objectwise intersect the optical axis at
a location Q between said fourth lens group and said fifth lens group,
vii) at least one of said fourth and fifth lens groups includes a second
aspherical surface arranged between said first aspherical surface and said aperture stop,
viii) said fifth lens group includes a third aspherical surface arranged
imagewise of said aperture stop, and

ix) wherein the following condition is satisfied:

$$0.01 < d_Q / \{L \times (1-NA)\} < 0.4$$

wherein the image and the object are separated by a distance L, said
location Q and said aperture stop are separated by a distance d_Q , and NA is an imagewise
numerical aperture of the projection optical system; and

c) exposing said photosensitive workpiece over an exposure field.

17. (Amended) A device manufacturing method comprising the steps of:

a) coating a photosensitive material onto a substrate;

b) projecting onto said substrate the image of a pattern of a reticle through

[the] a projection optical system, [set forth in claim 1] said projection optical system
comprising, along an optical axis:

- i) a first lens group having positive refractive power,
- ii) a second lens group having negative refractive power,
- iii) a third lens group having positive refractive power,
- iv) a fourth lens group having negative refractive power and a first aspherical surface,
- v) a fifth lens group having positive refractive power and an aperture stop,
- vi) wherein the projection optical system is designed such that paraxial rays traveling parallel to the optical axis imagewise to objectwise intersect the optical axis at a location Q between said fourth lens group and said fifth lens group,
- vii) at least one of said fourth and fifth lens groups includes a second aspherical surface arranged between said first aspherical surface and said aperture stop,
- viii) said fifth lens group includes a third aspherical surface arranged imagewise of said aperture stop, and
- ix) wherein the following condition is satisfied:
$$0.01 < d_Q / \{L \times (1-NA)\} < 0.4$$
wherein the image and the object are separated by a distance L, said location Q and said aperture stop are separated by a distance d_Q , and NA is an imagewise numerical aperture of the projection optical system; and

c) developing said photosensitive material on said substrate, thereby forming a photoresist pattern.

31. (Amended) A method of patterning a photosensitive workpiece over an exposure field with a pattern present on a reticle, the method comprising the steps of:

a) illuminating the reticle with light;

b) projecting the light from the reticle with [the] a projection optical system, [as set forth on claim 8] the projection optical system comprising, objectwise to imagewise, along an optical axis:

(i) a first lens group having positive refractive power,

(ii) a second lens group having negative refractive power,

(iii) a third lens group having positive refractive power,

(iv) a fourth lens group having negative refractive power and a first aspherical concave surface with refractive power at a paraxial region and refractive power at a periphery, wherein said refractive power at said periphery is weaker than said refractive power at said paraxial region,

(v) a second aspherical surface arranged imagewise of said first aspherical surface and having refractive power at a paraxial region and refractive power at a periphery, and being one of:

(a) a convex surface, with said refractive power at said periphery weaker than said refractive power at said paraxial region, and

(b) a concave surface, with said refractive power at said periphery stronger than said refractive power at said paraxial region,

(vi) a fifth lens group having positive refractive power, an aperture stop, and a third aspherical surface arranged imagewise of said aperture stop, wherein said third aspherical surface includes a paraxial region, a periphery and refractive power and is one of:

(a) a convex surface, with said refractive power at said periphery weaker than said refractive power at said paraxial region, and

(b) a concave surface, with said refractive power at said periphery stronger than said refractive power at said paraxial region, and

(vii) wherein the projection optical system is designed such that paraxial rays traveling parallel to the optical axis imagewise to objectwise intersect the optical axis at a location Q between said fourth lens group and said fifth lens group; and

c) exposing the photosensitive workpiece over the exposure field.

32. (Amended) A projection optical system [according to claim 1] comprising, along an optical axis:

i) a first lens group having positive refractive power,
ii) a second lens group having negative refractive power,
iii) a third lens group having positive refractive power,
iv) a fourth lens group having negative refractive power and a first aspherical surface,

v) a fifth lens group having positive refractive power and an aperture stop,

vi) wherein the projection optical system is designed such that paraxial rays traveling parallel to the optical axis imagewise to objectwise intersect the optical axis at a location Q between said fourth lens group and said fifth lens group,

vii) at least one of said fourth and fifth lens groups includes a second aspherical surface arranged between said first aspherical surface and said aperture stop,

viii) said fifth lens group includes a third aspherical surface arranged imagewise of said aperture stop, and

ix) wherein the following condition is satisfied:

$$0.01 < d_Q / \{L \times (1-NA)\} < 0.4$$

wherein the image and the object are separated by a distance L, said location Q and said aperture stop are separated by a distance d_Q, and NA is an imagewise numerical aperture of the projection optical system, wherein:

- (a) said first aspherical surface is concave and includes refractive power at a paraxial region and refractive power at a periphery, wherein said refractive power at said periphery is weaker than said refractive power at said paraxial region;
- (b) said second aspherical surface including refractive power at a paraxial region, and refractive power at a periphery, wherein said refractive power at said periphery is more negative than said refractive power at said paraxial region; and
- (c) said third aspherical surface including refractive power at a paraxial region, and refractive power at a periphery, wherein said refractive power at said periphery is more negative than said refractive power at said paraxial region.

38. (Amended) A method of [pattering] patterning a photosensitive workpiece with a pattern present on a reticle, the method comprising the steps of:

- (a) illuminating the reticle with light from [said] an illuminating optical system of [said] an exposure apparatus, [of claim 35] the exposure apparatus comprising:
 - (i) a first stage designed so as to be movable along a scanning direction and to support the reticle.

(ii) the illuminating optical system adjacent said first stage arranged so as to illuminate the reticle with light,

(iii) a second stage designed so as to be movable along at least said scanning direction, for supporting the photosensitive workpiece,

(iv) a projection optical system, arranged between said first stage and said second stage, having a plurality of lenses and an aperture stop, said plurality of lenses and said aperture stop designed such that said light from said reticle is capable of being guided to an exposure field on said substrate with an imagewise maximum numerical aperture of at least 0.8, and

(v) wherein said exposure field has a first dimension orthogonal to said scanning direction, and a second dimension along said scanning direction, said first dimension is greater than said second dimension, and said first dimension is at least 15mm;

(b) projecting the light from the reticle with the projection optical system of said exposure apparatus [of claim 35]; and

(c) exposing said photosensitive workpiece over said exposure field.

REMARKS

Claims 16-18, 31, 32 and 38 are pending. By this amendment, claims 16, 17, 31, 32 and 38 are rewritten in independent form. These claims were withdrawn by the Examiner in the parent application as a result of a restriction requirement.

Rule 53(b) Division of
Application No. 09/234,969
Filed January 21, 1999

Examination and allowance of these claims in due course are earnestly solicited.

Respectfully submitted,



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JAO:MAC/ccs

Date: November 28, 2000

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PROJECTION OPTICAL SYSTEM AND EXPOSURE APPARATUS AND METHOD**Field of the Invention**

The present invention relates to projection optical systems and exposure apparatus

5 incorporating same and methods pertaining to same, and in particular to such systems, apparatus and methods for manufacturing devices and elements, such as integrated circuits, liquid crystal displays, detectors, MR (magneto-resistive) heads, and the like.

Background of the Invention

10 Step-and-repeat and step-and-scan projection exposure apparatus are presently used to manufacture semiconductor devices and the like. In step and repeat projection exposure apparatus ("steppers"), each exposure field is exposed in a single static exposure. In step-and-scan projection exposure apparatus ("scanners"), each exposure field is scanned during exposure. A projection exposure apparatus as used in semiconductor manufacturing, for example, transfers an image of a pattern on a reticle, which is used as a mask, through a projection optical system and onto a wafer (or glass plate or like workpiece) coated with a photo-sensitive medium, such as photoresist. With the increasing miniaturization of the patterns of semiconductor integrated circuits and other similar devices, there is an increasing demand to increase the resolving power of projection optical systems incorporated into

15 projection exposure apparatus. The resolving power of the projection optical system can be increased by either shortening the exposure wavelength or increasing the image-side numerical aperture (NA).

20

The wavelengths used in projection exposure apparatus for semiconductor manufacturing are principally mercury lamp g-line ($\lambda = 436$ nm) to the i-line ($\lambda = 365$ nm). More recently, efforts are being made to employ shorter wavelength light sources, for example excimer lasers ($\lambda = 248$ nm, 193 nm). Consequently, projection optical systems are being developed that have optical characteristics that can be used with exposure light of short wavelength.

In addition, the demand for both increased resolving power and reduced image distortion in projection optical systems has increased. Image distortion as a whole includes several contributing factors, such as distortion inherent in the projection optical system, distortion due to warping of the wafer upon which the circuit pattern is printed, and distortion due to 5 warping of the reticle on which the circuit pattern to be imaged resides.

To reduce the effect of image distortion due to warping of the wafer, imagewise telecentric projection optical systems have been developed. In such systems, the exit pupil is located at infinity objectwise of the projection optical system. Likewise, to reduce image distortion due

10 to warpage of the reticle, objectwise telecentric optical systems have been employed, wherein the entrance pupil of the projection optical system is located at infinity imagewise of the projection optical system. Such projection optical systems are disclosed in, for example, Japanese Patent Application Kokai No. Sho 63-118115, United States patent No. 5,260,832 and Japanese Patent Application Kokai No. Hei 5-173065.

15

In addition, there have been demands for being able to select and adjust the NA to be more ideally suited for printing particular types of patterns on the reticle, as well as to account for other manufacturing conditions. In particular, there have been demands for the projection optical systems in exposure apparatus to have a variable aperture stop whose size can be

20

varied to change the NA of the projection optical system.

Also, if a plurality of lens surfaces in the projection optical system are made aspherical, it is possible to reduce the number of lenses used. Examples of such projection optical systems are disclosed in, for example, United States Patent No. 4,928,238, Japanese Patent

25

Application Kokai No. Hei 5-34593 and Japanese Patent Application Kokai No. Hei 7-128592.

As described above, it is desirable to make the projection optical system both imagewise and objectwise telecentric (i.e., "double-telecentric") to reduce the effects of both wafer warping 30 and reticle warping on image distortion. Therefore, as disclosed in the abovementioned patent applications, projection optical systems have been developed that are double-

telecentric. Nevertheless, in prior art double-telecentric projection optical systems, it has proven difficult to make the NA sufficiently large while simultaneously reducing the various aberrations over a large exposure field. In particular, in the prior art systems, distortion correction is generally inadequate.

5

Moreover, in the prior art projection optical systems, if a variable aperture stop is provided to vary the NA of the projection optical system, vignetting occurs at the periphery of the exposure field due to spherical aberration at the pupil when the aperture stop size is changed. Consequently, uniformity of illumination suffers in the exposure field periphery. In addition,

10 telecentricity degrades when the numerical aperture is varied, and there is also the problem that the exposure field size cannot be increased.

Furthermore, the projection optical systems with aspherical surfaces disclosed in the abovementioned patent applications introduce aspherical surfaces for the purpose of reducing

15 the overall glass thickness of the optical system and of improving transmittance. However, this has not lead to projection optical systems having large exposure regions and a sufficiently large numerical apertures.

Summary of the Invention

20 The present invention relates to projection optical systems and exposure apparatus incorporating same and methods pertaining to same, and in particular to such systems, apparatus and methods for manufacturing devices and elements, such as integrated circuits, liquid crystal displays, CCD (charge coupled device) detectors, MR (magneto-resistive) heads, and the like.

25

The present invention takes the above problems into consideration and has several objectives. The first objective to provide a compact high-performance projection optical system that is double-telecentric, and that includes an aperture stop capable of reducing the effects of vignetting when the numerical aperture (NA) is varied. A second objective is a projection 30 optical system that is extremely well-corrected for the various aberrations, particularly distortion, while ensuring, through the use of aspherical lens surfaces, a sufficiently large

numerical aperture and a large exposure field. A third objective to provide an exposure apparatus which includes with the abovementioned projection optical system, and a semiconductor device manufacturing method employing the exposure apparatus.

5 Accordingly, a first aspect of the present invention is a projection optical system capable of forming an image of an object. The system comprises, objectwise to imagewise, along an optical axis, a first lens group having positive refractive power, a second lens group having negative refractive power, a third lens group having positive refractive power, a fourth lens group having negative refractive power and a first aspherical surface, and a fifth lens group

10 having positive refractive power and an aperture. The projection optical system is designed such that paraxial rays traveling parallel to the optical axis imagewise to objectwise intersect the optical axis at a location Q between the fourth lens group and the fifth lens group. Further, at least one of the fourth and fifth lens groups includes a second aspherical surface arranged between the first aspherical surface in the fourth lens group and the aperture stop.

15 Also, the fifth lens group includes a third aspherical surface arranged imagewise of the aperture stop. In addition, the following condition is satisfied:

$$0.01 < d_Q / \{L \times (1 - NA)\} < 0.4 \quad (1)$$

20 wherein the image and the object are separated by a distance L, the location Q and the aperture stop are separated by a distance d_Q , and NA is an imagewise numerical aperture of the projection optical system.

25 A second aspect of the present invention is a projection optical system as described above, wherein the aperture stop has a variable size and is located imagewise of the location Q such that vignetting is minimized when the variable size is changed.

A third aspect of the invention is a projection optical system as described above, which satisfies the following conditions:

30

$$0.05 < f1/L < 0.5 \quad (2)$$

$$0.02 < -f_2/L < 0.2 \quad (3)$$

$$0.04 < f_3/L < 0.4 \quad (4)$$

$$0.03 < -f_4/L < 0.3 \quad (5)$$

$$0.04 < f_5/L < 0.4 \quad (6)$$

5

wherein f_1 through f_5 are focal lengths of the first through fifth lens groups, respectively.

A fourth aspect of the present invention is an exposure apparatus for imaging a pattern present on a reticle onto a photosensitive workpiece. The apparatus comprises a reticle stage 10 for supporting the reticle, an illumination optical system adjacent the reticle stage for illuminating the reticle, a workpiece stage for supporting a workpiece, and the projection optical system as described above arranged between the reticle stage and the workpiece stage.

A fifth aspect of the present invention is a method of patterning a photosensitive workpiece 15 with a pattern present on a reticle. The method comprises the steps of first illuminating the reticle, then projecting light from the reticle with the projection optical system as described above, and then exposing the photosensitive workpiece over an exposure field.

A sixth aspect of the present invention is a device manufacturing method comprising the 20 steps of first coating a photosensitive material onto a substrate, then projecting onto the substrate the image of a pattern of reticle through the projection optical system as described above, then developing the photosensitive material on the substrate, thereby forming a photoresist pattern.

25 **Brief Description of the Drawings**

FIG. 1 is a schematic optical diagram of the projection exposure apparatus of the present invention;

30 FIG. 2 is an optical diagram of the projection optical system of Working Example 1 of the present invention;

FIGS. 3A-3D are aberration plots for spherical aberration, astigmatism, distortion, and coma, respectively, for the projection optical system of FIG. 2;

5 FIG. 4 is an optical diagram of the projection optical system of Working Example 2 of the present invention;

FIGS. 5A-5D are aberration plots for spherical aberration, astigmatism, distortion, and coma, respectively, for the projection optical system of FIG. 4;

10 FIG. 6 is an optical diagram of the projection optical system of Working Example 3 of the present invention;

FIGS. 7A-7D are aberration plots for spherical aberration, astigmatism, distortion, and coma, respectively, for the projection optical system of FIG. 6;

15 FIG. 8 is an optical diagram of the projection optical system of Working Example 4 of the present invention;

FIGS. 9A-9D are aberration plots for spherical aberration, astigmatism, distortion, and coma, 20 respectively, for the projection optical system of FIG. 8; and

FIG. 10 is a flowchart of a preferred method of manufacturing a semiconductor device patterning a wafer with the exposure apparatus and projection optical system of the present invention.

25

Detailed Description of the Invention

The present invention relates to projection optical systems and exposure apparatus incorporating same and methods pertaining to same, and in particular to such systems, apparatus and methods for manufacturing devices and elements, such as integrated circuits, 30 liquid crystal displays, CCD (charge coupled device) detectors, MR (magneto-resistive) heads, and the like.

With reference to FIG. 1, exposure apparatus 10 includes a projection optical system PL having an object plane 12, an image plane 14, and an aperture stop AS disposed along an optical axis A. Projection optical system PL is substantially double-telecentric. Aperture stop AS is variable and disposed in the vicinity of the pupil position. An object, such as a 5 reticle R, is disposed at or near object plane 12. Object (mask, reticle, or original) R is typically a transparent substrate, such as fused silica, and includes a pattern (not shown) having small (i.e., micron and sub-micron) features. Object (reticle) R is held in place and moved into a position at or near object plane 12 by object (reticle) stage RS. Disposed adjacent object (reticle) R along optical axis A opposite projection lens PL is an illumination 10 optical system IS. The latter includes an exposure light source (not shown) for generating a light beam L.

Examples of exposure light sources are: a KrF excimer laser emitting light at a wavelength of 248.4 nm, an ArF laser emitting light at a wavelength of 193 nm, a F₂ laser emitting light at a 15 wavelength of 157 nm, the higher harmonics of a solid state laser (e.g. a YAG laser) emitting light at a wavelength of e.g. 248 nm, 193 nm, or 157 nm, or the various lines of a mercury arc lamp emitting a wavelength of, e.g., g-line, h-line, or i-line, mentioned above. Moreover, wavelengths associated with the higher harmonics converted from monochromatic laser light emitted from a DFB (distributed feedback) semiconductor laser or fiber laser into ultraviolet 20 light by a nonlinear optical crystal may be employed. For example, when the range of wavelengths of the monochromatic laser are set at 1.51 to 1.59 microns, eighth-order harmonics having a wavelength range from 189 nm to 199 nm can be obtained. Likewise, tenth-order harmonics having wavelength range 151 nm to 159 nm can also be obtained. In particular, when the wavelength range of the monochromatic laser are set at 1.544 to 1.553 25 microns, wavelengths in the range from 193 nm to 194 nm can be obtained (i.e., the same wavelengths as from an ArF excimer laser). When the wavelength range of the monochromatic laser is set at 1.57 to 1.58 microns, tenth-order harmonics having a wavelength range from 157 nm to 158 nm can be obtained (i.e., the same as from an F₂ laser). 30 Illumination optical system IS is designed to uniformly illuminate reticle R and also to form a source image at aperture stop AS in the absence of pattern of object (reticle) R (i.e., Kohler

illumination). A workpiece W, such as a silicon wafer coated with photoresist, is disposed along optical axis A at or near image plane 14. Workpiece (wafer) W is held in place and moved into position by a workpiece (wafer) stage WS.

5 Generally speaking, to pattern workpiece (wafer) W with exposure apparatus 10, object (reticle) R and workpiece (wafer) W are moved into proper alignment using object (reticle) stage RS and workpiece (wafer) stage WS, respectively. Object (reticle) R is then illuminated with illumination optical system IS for a certain amount of time. An image of the pattern on object (reticle) R is projected onto workpiece (wafer) W over an exposure field EF, via

10 projection lens PL. Workpiece (wafer) stage WS then moves an incremental amount and another exposure is made on workpiece (wafer) W. The process is repeated until a desired area of workpiece (wafer) W is exposed. Exposure apparatus 10 and methods associated therewith are discussed in further detail below.

15 In a preferred embodiment, reticle stage RS and workpiece (wafer) stage WS are moveable along a scanning direction (e.g., the X-direction), and exposure field EF has a first dimension orthogonal to the scanning direction (e.g., the Y-direction) and a second dimension in the scanning direction. Preferably, the first dimension is greater than the second dimension. Also, in a preferred embodiment, the first dimension is approximately at least 25 mm. In the

20 case where a stitching exposure is used, it is preferable that the first dimension be approximately at least 15mm when the exposure field EF has a trapezoid shape, hexangular shape, parallelogram shape, diamond shape, or other such polygonal shape. Such stitching exposure methods are disclosed in United States Patents No. 5,437,946, 5,477,304, and 5,617,182.

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Projection Optical System

With reference now to FIG. 2, the projection optical system of the present invention is described with reference to projection optical system 20 representing a Working Example 1 of the present invention. Projection optical system 20 comprises, in order from reticle R (i.e.,

30 object plane OP) to workpiece (wafer) W (i.e., image plane IP), or "objectwise to imagewise," a first lens group G1 having positive refractive power, a second lens group G2

having negative refractive power, a third lens group G3 having positive refractive power, a fourth lens group G4 having negative refractive power, and a fifth lens group G5 having positive refractive power.

- 5 Projection optical system 20 is double-telecentric and designed to operate at a particular exposure wavelength or a narrow band centered thereon (e.g., $\lambda = 248.4$ nm). A location Q wherein paraxial rays traveling parallel to optical axis A imagewise to objectwise intersect the optical axis is located between fourth lens group G4 and fifth lens group G5. A variable aperture stop AS for setting the NA is arranged imagewise of location Q in lens group G5.
- 10 As a result of this configuration, the difference in vignetting over the entire surface of the exposure field EF on workpiece (wafer) W (FIG. 1) is minimized.

With continuing reference to FIG. 2 and projection optical system 20, first lens group G1 contributes principally to the correction of distortion while maintaining telecentricity.

- 15 Second lens group G2 and fourth lens group G4 contribute principally to the correction of the Petzval sum and have the function of flattening image plane IP. Third lens group G3 generates positive distortion together with first lens group G1, and serves to correct negative distortion generated by second lens group G2, fourth lens group G4 and fifth lens group G5. Third lens group G3 and second lens group G2 constitute a telephoto system having a
- 20 positive-negative refractive power arrangement when viewed imagewise to objectwise. This combination prevents enlargement of projection optical system 20. To cope with the increased imagewise NA, fifth lens group G5 suppresses the generation of distortion particularly in the state wherein the generation of spherical aberration is minimized, guides the light beam onto workpiece (wafer) W, and serves the role of forming an image.

25

It is also preferable that the projection optical system of the present invention satisfy at least one of a number of design conditions set forth below.

The first condition (1) stipulates the requirements for facilitating double-telecentricity, as

- 30 well as for reducing the effects of vignetting in the exposure field. Condition (1) is expressed as

$$0.01 < d_Q / \{L \times (1 - NA)\} < 0.4 \quad (1)$$

wherein L is the distance from object plane OP to image plane IP, NA is the imagewise numerical aperture, and d_Q is the axial distance from location Q to aperture stop AS (positive 5 when measured from location Q imagewise).

If $d_Q / \{L \times (1 - NA)\}$ exceeds the upper limit in condition (1) pupil aberration increases excessively and it is difficult to obtain double-telecentricity. Conversely, if $d_Q / \{L \times (1 - NA)\}$ falls below the lower limit in condition (1), overcorrection of pupil 10 aberration results as the Petzval sum approaches zero, which enlarges the projection optical system.

It is also preferable in the projection optical system of the present invention that variable aperture stop AS be arranged imagewise of location Q. This minimizes the difference in 15 vignetting over the exposure field when the NA is changed by varying the size of aperture stop AS. With continuing reference to FIG. 2, the advantage of this configuration can be understood by considering a parallel light beam (not shown) entering projection optical system 20 imagewise to objectwise. The paraxial principle rays of this beam intersect optical axis A at location Q, due to refraction of the positive lenses imagewise of location Q. Since 20 these positive lenses have positive refractive power, a parallel light beam impinging thereon at a predetermined angle with respect to optical axis A forms an image at a position imagewise from location Q. Accordingly, if aperture stop AS is located imagewise of location Q, the effect of vignetting at the periphery of the exposure field due to the field 25 curvature of the pupil can, for practical purposes, be adequately controlled. Also, the various aberrations can be satisfactorily corrected, even if the size of aperture stop AS is varied.

The second design condition stipulates the optimal refractive power range for first lens group G1 and is expressed as:

$$30 \quad 0.05 < f1/L < 0.5 \quad (2)$$

wherein f_1 is the focal length of first lens group G1. If f_1/L exceeds the upper limit in condition (2), positive distortion generated by first lens group G1 cannot be fully corrected by the negative distortion generated by second, fourth and fifth lens groups G2, G4 and G5.

Conversely, if f_1/L falls below the lower limit in condition (2), high-order positive distortion

5 is generated.

A third design condition stipulates the optimal refractive power range for second lens group G2 and is expressed as:

10 $0.02 < -f_2/L < 0.2$ (3)

wherein f_2 is the focal length of second lens group G2. If $-f_2/L$ exceeds the upper limit in condition (3), the correction of the Petzval sum is not sufficiently corrected, making it difficult to flatten the image plane. Conversely, if $-f_2/L$ falls below the lower limit in

15 condition (3), the generation of negative distortion increases, and it becomes difficult to satisfactorily correct such a large negative distortion by just first and third lens groups G1 and G3.

A fourth design condition stipulates the optimal refractive power range for third lens

20 group G3 and is expressed as:

$0.04 < f_3/L < 0.4$ (4)

wherein f_3 is the focal length of third lens group G3. If f_3/L exceeds the upper limit in

25 condition (4), the projection optical system increases in size, since the telephoto ratio of the telephoto system formed by second lens group G2 and third lens group G3 increases. In addition, positive distortion generated by third lens group G3 decreases, and negative distortion generated by second, fourth and fifth lens groups G2, G4 and G5 can no longer be satisfactorily corrected. Conversely, if f_3/L falls below the lower limit in condition (4),
30 satisfactory imaging performance can no longer be obtained due to the generation of high-order spherical aberration.

A fifth design condition stipulates the optimal refractive power range for fourth lens group G4 and is expressed as:

$$0.03 < -f4/L < 0.3 \quad (5)$$

5

wherein f_4 is the focal length of fourth lens group G4. If $-f_4/L$ exceeds the upper limit in condition (5), the Petzval sum not sufficiently corrected, making it difficult to achieve a flat image plane. Conversely, if $-f_4/L$ falls below the lower limit in condition (5), high-order spherical aberration and coma is generated.

10

A sixth design condition stipulates the optimal refractive power of fifth lens group G5 is expressed as:

$$0.04 < f5/L < 0.4 \quad (6)$$

15

wherein f_5 is the focal length of fifth lens group G5. If f_5/L exceeds the upper limit in condition (6), the overall refractive power of fifth lens group G5 is excessively weak, which enlarges the projection optical system. Conversely, if f_5/L falls below the lower limit in condition (6), high-order spherical aberration is generated and image contrast deteriorates.

20

In addition to satisfying at least one of the above design conditions, it is also preferable that the projection optical system of the present invention have one or more aspherical surfaces, each having a paraxial (i.e., near-axis) region, a periphery (i.e., the portion of the surface farthest from the axis), and refractive power.

25

With continuing reference to projection optical system 20 of FIG. 2, in a first preferred embodiment, fourth lens group G4 has at least one aspherical surface ASP1, and fourth or fifth lens group G4 or G5 has at least one aspherical surface ASP2 arranged between aspherical surface ASP1 and aperture stop AS. In addition, fifth lens group G5 has at least 30 one aspherical surface ASP3 arranged imagewise of aperture stop AS.

By arranging at least one aspherical surface (e.g., ASP1) in fourth lens group G4, it becomes possible to suppress the generation of field angle-related aberrations (sagittal coma, in particular), which has a tendency to remain in bright (i.e., large NA) dioptic optical systems comprising only spherical surfaces. It is preferable that aspherical surface ASP1 is concave, 5 and that it have a shape at the lens periphery that weakens the refractive power relative to that at the paraxial region. Namely, it is preferred that aspherical surface ASP1 be such that the refractive power at the periphery be more negative than the refractive power at the paraxial region.

10 It is also preferable to arrange aspherical surface ASP2 between aspherical surface ASP1 and aperture stop AS in fourth lens group G4 and fifth lens group G5, and to arrange aspherical surface ASP3 in fifth lens group G5 imagewise of aperture stop AS. This arrangement makes it possible to correct aberrations introduced by the aspherical surfaces before and after aperture stop AS, and to correct high-order spherical aberration without worsening distortion 15 and coma.

With continuing reference to FIG. 2, in one preferred embodiment, aspherical surface ASP1 is concave such that the refractive power at the periphery is weaker than that in the paraxial region. It is also preferred that aspherical surface ASP2 be either convex such that the 20 refractive power at the periphery is weaker than that at the paraxial region, or concave such that the refractive power at the periphery is stronger than that in the paraxial region. Namely, it is preferred that aspherical surface ASP2 be such that the refractive power at the periphery be more negative than the refractive power at the paraxial region.

25 In another preferred embodiment, aspherical surface ASP3 is either convex such that the refractive power at the periphery is weaker than that at the paraxial region or concave such that the refractive power at the periphery is stronger than that at the paraxial region. Namely, it is preferred that aspherical surface ASP3 be such that refractive power at the periphery be more negative than refractive power at the paraxial region. In this case, it is preferable to set 30 the refractive power at the periphery such that it returns slightly in the direction of the refractive power in the paraxial region.

In addition to the above preferred embodiments, it is also preferable in the present invention if additional aspherical surfaces are arranged outside of fourth lens group G4 and fifth lens group G5, i.e., in first, second and third groups G1, G2 and G3, since such arrangement is effective for further correcting aberrations.

5

Accordingly, with reference now to FIG. 4 and projection optical system 40, in another preferred embodiment of the present invention, the projection optical system includes aspheric surfaces ASP1-ASP3, as described above, and further includes least one aspherical surface ASP4 in first lens group G1. This arrangement facilitates correcting distortion.

10

With reference now to FIG. 6 and projection optical system 60, in a further preferred embodiment of the present invention, the projection optical system includes aspheric surfaces ASP1-ASP3, as described above, and further includes least one aspherical surface ASP5 in second lens group G2. This arrangement facilitates correcting entrance pupil aberration
15 (displacement of the entrance pupil as a function of object height).

20

With reference now to FIG. 8 and projection optical system 80, in another preferred embodiment of the present invention, the projection optical system includes aspheric surfaces ASP1-ASP3, as described above, and further includes least one aspherical surface ASP6 in third lens group G3. This arrangement facilitates correcting coma.

25

With reference again to FIG. 1, since a double-telecentric projection optical system with a high NA can be provided in exposure apparatus 10, high resolution is obtained and the projection magnification does not change even if warpage of object (reticle) R and/or workpiece (wafer) W occurs. Accordingly, exposure can be performed at a high resolving power and with no image distortion. In addition, large chip patterns can be exposed at one time, since a large exposure field EF is possible.

Working Examples of the Projection Optical System

30

Four Working Examples are set forth below in Tables 1-4 which set forth the design specifications (Tables 1A- 4A), values of the aspherical surface coefficients for the aspheric

surfaces (Tables 1B- 4B), and values for the parameters and design conditions of Working Examples 1-4 (Tables 1C- 4C). In Tables 1A- 4A, D0 is the axial distance from object (reticle) R to the most objectwise lens surface of first lens group G1, WD is the axial distance (working distance) from the most imagewise lens surface of fifth lens group G5 to workpiece

5 (wafer) W, β is the projection magnification of the projection optical system, NA is the image-side numerical aperture of the projection optical system, d_{EX} is the diameter of exposure field EF on workpiece (wafer) W (see FIG. 1), and L is the axial distance between the object (reticle) R (i.e., object plane OP) and workpiece (wafer) W (i.e., image plane IP). In Tables 1A-4A, S is the surface number of the optical components arranged objectwise to

10 imagewise, r is the radius of curvature of the corresponding lens surface, d is the axial distance between adjacent lens surfaces, n is the refractive index of the glass at wavelength $\lambda = 248.4$ nm. Silica glass, for example, can be used as the glass material. The unit of measurement of the radius of curvature r and the axial distance d is millimeters, for example.

15

Also, in Tables 1B-4B, "E" denotes "exponential" such that "En" means " 10^n ".

The expression for an aspherical surface is as follows:

20
$$Z = \{ch^2/(1 + \sqrt{[1 - (1 + \kappa)c^2h^2]})\} + Ah^4 + Bh^6 + Ch^8 + Dh^{10} + Eh^{12} + Fh^{14}$$

wherein Z is the amount of sag of a surface parallel to the optical axis, c is the curvature at the apex of the surface, h is the distance from the optical axis, and κ is the conical coefficient.

The letters A, B, C, D, E, F are aspherical surface coefficients.

25

In the Working Examples below, if the maximum value of the $NA = NA_{\text{MAX}} = 0.8$ and the variable range of the NA is set to approximately 60% of the maximum value, then the variable range of NA due to varying the size of aperture stop AS becomes approximately $0.5 \leq NA \leq 0.8$ (i.e., $0.6 \times NA_{\text{MAX}} \leq NA \leq NA_{\text{MAX}}$).

30

FIGS. 3A-3D, 5A-5D, 7A-7D and 9A-9D are aberration plots for spherical aberration (3A-9A), astigmatism (3B-9B), distortion (3C-9C) and coma (tangential and sagittal) (3D-9D) for Working Examples 1-4, respectively. In each aberration plot, Y is the image height. In the astigmatism plots (3B-9B), the broken line represents the tangential image plane and the solid line represents the sagittal image plane.

Working Example 1

With reference to FIG. 2, projection optical system 20 represents Working Example 1 of the present invention. Projection optical system 20 is double-telecentric and comprises, 10 objectwise to imagewise, as described above, a first lens group G1 having positive refractive power, a second lens group G2 having negative refractive power, a third lens group G3 having positive refractive power, a fourth lens group G4 having negative refractive power, and a fifth lens group G5 having positive refractive power. Projection optical system 20 is double-telecentric. Location Q is located between fourth lens group G4 and fifth lens 15 group G5, and variable aperture stop AS is arranged imagewise of location Q. This configuration minimizes the difference in vignetting over the entire surface of exposure field EF (FIG. 1) on workpiece (wafer) W.

Projection optical system 20 further comprises an aspherical surface ASP1 located in fourth 20 lens group G4, an aspherical surface ASP2 arranged between aspherical surface ASP1 and aperture stop AS, and an aspherical surface ASP3 arranged in fifth lens group G5 imagewise of aperture stop AS.

25 TABLE 1A - DESIGN SPECIFICATIONS FOR WORKING EXAMPLE 1

D₀ = 56.938
 WD = 8.558
 $|\beta| = 1/4$
 Maximum NA = 0.8
 $d_{EX} = 26.4$
 L = 1189.996

S	r	d	n	
1	-255.627	13.000	1.50839	

	2	306.419	8.567	1	
	3	1565.905	26.363	1.50839	
	4	-286.322	1.000	1	
	5	828.381	24.476	1.50839	
5	6	-314.474	1.000	1	
	7	332.392	29.451	1.50839	
	8	-407.364	1.000	1	
	9	271.626	17.000	1.50839	
10	10	204.642	6.844	1	
	11	311.458	31.538	1.50839	
	12	-295.797	1.000	1	
	13	-2000.000	12.436	1.50839	
	14	152.723	25.832	1	
15	15	-224.897	12.000	1.50839	
	16	194.016	23.075	1	
	17	-228.159	12.500	1.50839	
	18	750.000	29.560	1	
	19	-125.249	18.000	1.50839	
20	20	-456.292	6.197	1	
	21	-316.444	29.551	1.50839	
	22	-168.563	1.000	1	
	23	∞	40.572	1.50839	
	24	-267.422	1.000	1	
	25	2178.298	44.226	1.50839	
25	26	-317.500	1.000	1	
	27	309.182	47.253	1.50839	
	28	-1355.659	1.000	1	
	29	171.033	46.299	1.50839	

	30	475.084	20.092	1	
	31	465.958	20.807	1.50839	
	32	118.116	46.763	1	
5	33	-211.023	12.000	1.50839	(ASP1)
	34	186.008	44.783	1	
	35	-120.544	12.850	1.50839	
	36	∞	11.955	1	
10	37	-477.419	39.938	1.50839	(ASP2)
	38	-169.642	4.108	1	
	39	∞	8.892	1	(Q)
	40	684.757	40.830	1.50839	
	41	-391.691	0.000	1	
	42	∞	9.043	1	(AS)
15	43	1500.000	49.893	1.50839	
	44	-274.486	12.401	1	
	45	-214.316	27.250	1.50839	
	46	-282.306	10.000	1	
	47	260.941	40.402	1.50839	
20	48	1227.057	1.000	1	
	49	188.000	39.918	1.50839	
	50	444.771	1.000	1	
	51	178.000	29.205	1.50839	
	52	308.876	1.000	1	
	53	149.162	33.190	1.50839	
25	54	476.624	3.871	1	(ASP3)
	55	613.189	24.077	1.50839	
	56	65.511	6.493	1	
	57	66.070	60.000	1.50839	

58	367.843	(WD)	1	
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TABLE 1B: VALUES OF ASPHERICAL COEFFICIENTS

5 **Surface ASP1**

$$c = -4.73883E-04$$

$$\kappa = 1.212633$$

$$A = -1.37869E-08$$

$$B = 3.11693E-12$$

$$C = 5.04656E-17$$

$$D = 6.46573E-22$$

$$E = -3.20804E-25$$

$$F = 1.66371E-29$$

10 **Surface ASP2**

$$c = 2.09459E-03$$

$$\kappa = -0.419761$$

$$A = -3.03031E-09$$

$$B = -3.82761E-13$$

$$C = 4.92647E-18$$

$$D = -1.27524E-21$$

$$E = 1.11209E-25$$

$$F = -4.75978E-30$$

15 **Surface ASP3**

$$c = 2.09809E-03$$

$$\kappa = 0$$

$$A = 6.78816E-09$$

$$B = 9.68697E-13$$

$$C = -5.23581E-17$$

$$D = 1.18829E-21$$

$$E = 0$$

$F = 0$

5 TABLE 1C: PARAMETERS AND DESIGN CONDITION VALUES

(1) $0.084 \leq d_Q / \{L \times (1-NA)\} \leq 0.209$

(2) $f1/L = 0.125$

(3) $-f2/L = 0.046$

(4) $f3/L = 0.102$

10 (5) $-f4/L = 0.079$

(6) $f5/L = 0.109$

$f1 = 148.730$

$f2 = -54.952$

15 $f3 = 120.942$

$f4 = -93.589$

$f5 = 129.783$

$L = 1189.996$

$d = 49.722$

20 $NA = 0.8 \sim 0.5$

As can be seen from aberration plots 3A-3D for Working Example 1 of the present invention, distortion in particular is satisfactorily corrected over the entire large exposure region, and other aberrations are also well corrected with good balance. In addition, even though projection optical system 20 is double-telecentric with a maximum value of the $NA = 0.8$, the effects of vignetting are small, and the various aberrations remain satisfactorily corrected even if the NA is greatly changed. The present Working Example can be applied to a slit-like (rectangular) shape exposure field (e.g., 26mm x 8mm, or 26mm x 5mm).

30

Working Example 2

With reference to FIG. 4, projection optical system 40 represents Working Example 2 of the present invention, and has essentially the same basic configuration of lens groups as projection optical system 20 of FIG. 2, including the locations of aspherical surfaces ASP1-

APS3. Projection optical system 40 further includes an aspherical surface ASP4 arranged in first lens group G1.

5 TABLE 2A - DESIGN SPECIFICATIONS FOR WORKING EXAMPLE 2

10
15
20
25
30

D₀ = 56.937
 WD = 8.556
 $|\beta| = 1/4$
 Maximum NA = 0.8
 d_{EX} = 26.4
 L = 1190.293

S	r	d	n	
1	-255.794	13.000	1.50839	
2	304.711	8.549	1	(ASP4)
3	1523.076	26.352	1.50839	
4	-290.961	1.000	1	
5	707.183	24.451	1.50839	
6	-337.153	1.000	1	
7	342.978	29.211	1.50839	
8	-406.487	1.000	1	
9	262.194	17.000	1.50839	
10	192.603	6.830	1	
11	282.569	31.441	1.50839	
12	-296.721	1.000	1	
13	-2000.000	12.774	1.50839	
14	156.410	25.862	1	
15	-217.396	12.000	1.50839	
16	193.187	23.071	1	
17	-229.962	12.500	1.50839	
18	753.548	29.591	1	
19	-125.018	18.000	1.50839	

	20	-470.631	6.215	1	
	21	-322.848	29.532	1.50839	
	22	-168.545	1.000	1	
	23	∞	40.488	1.50839	
5	24	-267.922	1.000	1	
	25	2058.177	44.221	1.50839	
	26	-319.862	1.000	1	
	27	308.013	47.495	1.50839	
	28	-1379.214	1.000	1	
10	29	171.065	46.313	1.50839	
	30	475.356	20.101	1	
	31	465.085	20.822	1.50839	
	32	118.145	46.805	1	
	33	-210.732	12.000	1.50839	(ASP1)
15	34	186.081	44.774	1	
	35	-120.565	12.850	1.50839	
	36	∞	11.978	1	
	37	-477.987	39.928	1.50839	(ASP2)
	38	-169.679	4.102	1	
20	39	∞	8.911	1	(Q)
	40	682.568	40.816	1.50839	
	41	-391.897	0.000	1	
	42	∞	9.070	1	(AS)
	43	1500.000	49.868	1.50839	
25	44	-274.701	12.416	1	
	45	-214.373	27.250	1.50839	
	46	-282.422	10.000	1	
	47	260.913	40.405	1.50839	

48	1226.772	1.000	1	
49	188.000	39.907	1.50839	
50	444.503	1.000	1	
51	178.000	29.185	1.50839	
52	308.504	1.000	1	
53	149.159	33.191	1.50839	
54	474.418	3.897	1	(ASP3)
55	612.596	24.177	1.50839	
56	65.478	6.451	1	
57	66.000	60.000	1.50839	
58	368.643	(WD)	1	

TABLE 2B: VALUES OF ASPHERICAL COEFFICIENTS

Surface ASP1

c = -4.74536E-03

κ = 1.223505

A = -1.41105E-08

B = 3.15056E-12

C = 5.33738E-17

D = 6.14925E-22

E = -3.11253E-25

F = 1.59082E-29

Surface ASP2

c = -2.09211E-03

κ = -0.445417

A = -2.99871E-09

B = -3.87784E-13

C = 4.85381E-18

D = -1.27131E-21

	E = 1.09975E-25
	F = -4.70926E-30
5	Surface ASP3
	c = 2.10785E-03
	$\kappa = 0$
	A = 6.70585E-09
	B = 9.66412E-13
10	C = -5.16458E-17
	D = 1.16221E-21
	E = 0
	F = 0
15	Surface ASP4
	c = 3.28179E-03
	$\kappa = 0$
	A = -3.81013E-09
20	B = 2.15522E-13
	C = 7.31492E-18
	D = -1.31012E-21
	E = 0
	F = 0
25	

TABLE 2C: PARAMETERS AND DESIGN CONDITION VALUES

	(1) $0.084 \leq d_Q/\{L \times (1-NA)\} \leq 0.209$
30	(2) $f1/L = 0.125$
	(3) $-f2/L = 0.046$
	(4) $f3/L = 0.101$
	(5) $-f4/L = 0.079$
	(6) $f5/L = 0.109$

	$f_1 = 148.873$
	$f_2 = -54.783$
	$f_3 = 120.796$
5	$f_4 = -93.618$
	$f_5 = 129.808$
	$L = 1190.293$
10	$d = 49.726$
	$NA = 0.8 \sim 0.5$

As can be seen from aberration plots 5A-5D for Working Example 2 of the present invention, distortion in particular is satisfactorily corrected over the entire large exposure region, and other aberrations are also well corrected with good balance. In addition, even though

15 projection optical system 40 is double-telecentric with a maximum value of the $NA = 0.8$, the effects of vignetting are small, and the various aberrations remain satisfactorily corrected even if the NA is greatly changed. The present Working Example can be applied to a slit-like (rectangular) shape exposure field (e.g., 26m x 8 mm or 26mm x 5mm).

20 Working Example 3

With reference to FIG. 6, projection optical system 60 represents Working Example 3 of the present invention, and has essentially the same basic configuration of lens groups as projection optical system 20 of FIG. 2, including the locations of aspherical surfaces ASP1-ASP3. Projection optical system 60 further includes an aspherical surface ASP5 is arranged 25 in second lens group G1.

TABLE 3A - DESIGN SPECIFICATIONS FOR WORKING EXAMPLE 3

$D_0 = 56.947$
 $WD = 7.678$
 $|\beta| = 1/4$
 Maximum NA = 0.8
 $d_{EX} = 26.4$
 $L = 1191.307$

S	r	d	n	
1	-295.194	13.000	1.50839	
2	307.090	11.543	1	
3	2094.974	20.585	1.50839	
4	-308.498	1.000	1	
5	798.586	25.527	1.50839	
6	-348.935	1.000	1	
7	421.955	28.789	1.50839	
8	-335.489	1.000	1	
9	281.085	17.000	1.50839	
10	210.236	3.852	1	
11	248.819	31.665	1.50839	
12	-312.999	1.000	1	
13	-2000.000	12.729	1.50839	
14	150.843	27.217	1	
15	-203.928	12.000	1.50839	
16	167.173	26.604	1	
17	-208.236	12.500	1.50839	
18	957.666	24.946	1	(ASP5)
19	-147.060	18.000	1.50839	
20	-378.007	7.483	1	
21	-258.912	25.237	1.50839	
22	-168.885	1.000	1	

	23	∞	40.270	1.50839	
	24	-266.905	1.000	1	
	25	1909.000	44.411	1.50839	
	26	-318.771	1.000	1	
5	27	281.823	48.046	1.50839	
	28	-2703.904	1.000	1	
	29	173.110	46.118	1.50839	
	30	491.765	23.296	1	
	31	475.493	20.366	1.50839	
10	32	120.322	46.663	1	
	33	-209.981	12.000	1.50839	(ASP1)
	34	197.000	45.464	1	
	35	-114.299	12.850	1.50839	
	36	-5000.000	11.908	1	
15	37	-478.278	42.997	1.50839	(ASP2)
	38	-169.870	4.260	1	
	39	∞	8.837	1	(Q)
	40	683.041	40.543	1.50839	
	41	-386.391	0.000	1	
20	42	∞	8.716	1	(AS)
	43	1378.469	47.021	1.50839	
	44	-287.893	17.279	1	
	45	-214.067	27.250	1.50839	
	46	-277.449	10.000	1	
25	47	260.145	42.695	1.50839	
	48	1760.879	1.000	1	
	49	189.250	38.807	1.50839	
	50	444.163	1.000	1	

51	180.000	27.895	1.50839	
52	297.607	1.000	1	
53	155.389	32.579	1.50839	
54	496.127	4.141	1	(ASP3)
55	712.002	27.982	1.50839	
56	65.481	4.652	1	
57	66.000	59.959	1.50839	
58	441.381	(WD)	1	

10 TABLE 3B: VALUES OF ASPHERICAL COEFFICIENTS

15 **Surface ASP1**

c = -4.76234E-03

κ = 0.861651

A = -7.84820E-09

B = 3.01423E-12

C = 9.70754E-17

D = 1.62617E-21

E = -2.56672E-25

F = 1.42087E-29

20 **Surface ASP2**

25 c = -2.09084E-03

κ = 2.804972

A = -8.77018E-09

B = -4.80478E-13

C = -3.02578E-18

30 D = -2.74308E-21

E = 2.11317E-25

F = -1.37915E-29

	Surface ASP3
	$c = 2.01561E-03$
5	$\kappa = 0$
	$A = 5.23214E-10$
	$B = 1.19414E-12$
	$C = -5.86228E-17$
	$D = 1.24893E-21$
10	$E = 0$
	$F = 0$
	Surface ASP5
15	$c = 1.04421E-03$
	$\kappa = 0$
	$A = -2.65532E-08$
	$B = -4.16828E-13$
	$C = 5.01741E-18$
20	$D = -6.52068E-21$
	$E = 7.82794E-25$
	$F = -6.18178E-29$

	TABLE 3C: PARAMETERS AND DESIGN CONDITION VALUES
	(1) $0.083 \leq d_Q/\{L \times (1-NA)\} \leq 0.207$
	(2) $f1/L = 0.123$
	(3) $-f2/L = 0.047$
25	(4) $f3/L = 0.104$
	(5) $-f4/L = 0.080$
	(6) $f5/L = 0.110$
	$f1 = 145.982$
30	$f2 = -56.252$
	$f3 = 123.837$

5	$f_4 = -94.933$
	$f_5 = 131.432$
	$L = 1191.307$
	$d = 49.380$
	$NA = 0.8 \sim 0.5$

As can be seen from aberration plots 7A-7D for Working Example 3 of the present invention, distortion in particular is satisfactorily corrected over the entire large exposure region, and other aberrations are also well corrected with good balance. In addition, even though

10 projection optical system 60 is double-telecentric with a maximum value of the $NA = 0.8$, the effects of vignetting are small, and the various aberrations remain satisfactorily corrected even if the NA is greatly changed. The present Working Example can be applied to a slit-like (rectangular) shape exposure field (e.g., 26mm x 8mm or 26mm x 5mm).

15 Working Example 4

With reference to FIG. 8, projection optical system 80 represents Working Example 4 of the present invention, and has essentially the same basic configuration of lens groups as projection optical system 20 of FIG. 2, including the locations of aspherical surfaces ASP1-APS3. Projection optical system 60 further includes an aspherical surface ASP6 is arranged

20 in third lens group G1.

TABLE 4A - DESIGN SPECIFICATIONS FOR WORKING EXAMPLE 4

25	$D_0 = 56.195$ $WD = 8.547$ $ \beta = 1/4$ Maximum $NA = 0.8$ $d_{EX} = 26.4$ $L = 1189.851$																				
30	<table border="1"> <thead> <tr> <th>S</th><th>r</th><th>d</th><th>n</th><th></th></tr> </thead> <tbody> <tr> <td>1</td><td>-281.019</td><td>13.000</td><td>1.50839</td><td></td></tr> <tr> <td>2</td><td>316.929</td><td>8.609</td><td>1</td><td></td></tr> <tr> <td>3</td><td>2500.000</td><td>26.225</td><td>1.50839</td><td></td></tr> </tbody> </table>	S	r	d	n		1	-281.019	13.000	1.50839		2	316.929	8.609	1		3	2500.000	26.225	1.50839	
S	r	d	n																		
1	-281.019	13.000	1.50839																		
2	316.929	8.609	1																		
3	2500.000	26.225	1.50839																		

	4	-303.360	1.000	1	
	5	804.062	24.227	1.50839	
	6	-318.842	1.000	1	
	7	354.459	29.152	1.50839	
5	8	-377.293	1.000	1	
	9	263.543	17.000	1.50839	
	10	199.659	6.604	1	
	11	295.344	30.241	1.50839	
	12	-307.153	1.074	1	
10	13	-2000.000	13.052	1.50839	
	14	152.095	25.535	1	
	15	-226.948	12.000	1.50839	
	16	199.970	23.919	1	
	17	-200.430	12.500	1.50839	
15	18	750.000	29.580	1	
	19	-134.929	18.000	1.50839	
	20	-423.324	6.957	1	
	21	-286.676	29.399	1.50839	
	22	-167.682	1.000	1	
20	23	∞	40.813	1.50839	
	24	-266.938	1.000	1	
	25	3220.051	42.890	1.50839	
	26	-317.569	1.000	1	
	27	302.026	48.170	1.50839	
25	28	-1518.815	1.000	1	(ASP6)
	29	171.737	46.214	1.50839	
	30	481.358	20.022	1	
	31	458.364	20.729	1.50839	

32	121.840	46.884	1	
33	-203.076	12.000	1.50839	(ASP1)
34	185.000	45.147	1	
35	-121.196	12.850	1.50839	
36	∞	11.728	1	
37	-465.519	39.959	1.50839	(ASP2)
38	-170.031	4.118	1	
39	∞	8.882	1	(Q)
40	663.260	40.673	1.50839	
41	-392.224	0.000	1	
42	∞	9.244	1	(AS)
43	1492.727	49.719	1.50839	
44	-277.593	12.757	1	
45	-214.522	27.250	1.50839	
46	-282.481	10.000	1	
47	261.717	41.243	1.50839	
48	1246.120	1.000	1	
49	188.000	39.612	1.50839	
50	439.103	1.000	1	
51	178.000	29.125	1.50839	
52	307.599	1.000	1	
53	147.699	33.313	1.50839	
54	461.089	4.088	1	(ASP3)
55	612.505	24.500	1.50839	
56	65.463	6.105	1	
57	66.000	60.000	1.50839	
58	373.143	(WD)	1	

TABLE 4B: VALUES OF ASPHERICAL COEFFICIENTS

5

Surface ASP1

$c = -4.92426E-03$

$\kappa = 1.140743$

$A = -1.17013E-08$

$B = 2.95847E-12$

$C = 7.22796E-17$

10

$D = 3.50053E-21$

$E = -4.73158E-25$

$F = 1.77468E-29$

15

Surface ASP2

$c = -2.14814E-03$

$\kappa = -0.511241$

$A = -2.90908E-09$

20

$B = -3.82923E-13$

$C = 9.51818E-19$

$D = -1.02058E-21$

$E = 7.38868E-26$

$F = -3.11809E-30$

25

Surface ASP3

$c = 2.16878E-03$

$\kappa = 0$

$A = 6.88715E-09$

30

$B = 8.36584E-13$

$C = -4.26325E-17$

$D = 9.02955E-22$

$E = 0$

$F = 0$

	Surface ASP6
	$c = -6.58408E-04$
5	$\kappa = 0$
	$A = -1.29700E-09$
	$B = -2.23515E-14$
	$C = 2.71217E-19$
	$D = 4.78605E-24$
10	$E = 0$
	$F = 0$

	TABLE 4C: PARAMETERS AND DESIGN CONDITION VALUES
	(1) $0.084 \leq d_Q/\{L \times (1-NA)\} \leq 0.208$
15	(2) $f1/L = 0.125$
	(3) $-f2/L = 0.047$
	(4) $f3/L = 0.103$
20	(5) $-f4/L = 0.079$
	(6) $f5/L = 0.109$
	$f1 = 148.857$
	$f2 = -55.987$
25	$f3 = 122.578$
	$f4 = -93.819$
	$f5 = 130.011$
	$L = 1189.851$
	$d = 49.554$
30	$NA = 0.8 \sim 0.5$

As can be seen from aberration plots 9A-9D for Working Example 4 of the present invention, distortion in particular is satisfactorily corrected over the entire large exposure region, and other aberrations are also well corrected with good balance. In addition, even though

projection optical system 60 is double-telecentric with a maximum value of the NA = 0.8, the effects of vignetting are small, and the various aberrations remain satisfactorily corrected even if the NA is greatly changed. The present Working Example can be applied to a slit-like (rectangular) shape exposure field (e.g., 26mm x 8mm or 26mm x 5mm).

5

It will be apparent to one skilled in the art that the abovementioned modes for carrying out the present invention is not limited to a particular wavelength or narrow band centered thereon. For example, the present invention can be applied to an ultraviolet wavelength of $\lambda = 248.4$ nm (e.g., from a KrF laser), or deep ultraviolet light of $\lambda = 193$ nm (e.g., from an

10 ArF laser), $\lambda = 157$ nm (e.g., from an F₂ laser), and $\lambda = 147$ nm (e.g., from a Kr₂ laser). In addition, the present invention can be applied to other wavelengths in the ultraviolet region like the g-line ($\lambda = 435.8$ nm wavelength) and i-line ($\lambda = 365.0$ nm wavelength) of mercury lamps, the higher harmonics of YAG lasers (e.g., $\lambda = 248$ nm, 193nm, or 157nm) and the like. In addition, other glass types besides quartz, such as fluorite (calcium fluoride, CaF₂), barium 15 fluoride (BaF₂), lithium fluoride (LiF) and magnesium fluoride (MgF₂) can also be used.

The embodiments of the present invention were described above in connection with step-and-scan projection exposure apparatus. However, the projection optical system of present invention can be applied to step-and-repeat projection exposure apparatus as well. In this case, the exposure field can use, e.g., a square shape, or rectangular shape inside a circular 20 area of diameter 26.4mm. In addition, though the projection magnification (lateral magnification) of the above embodiments and Working Examples is a reduction magnification, the present invention can be applied to unit magnification, or enlargement magnification.

25 **Semiconductor Device Manufacturing Method**

The present invention includes a method of patterning a workpiece using exposure apparatus 10 of FIG. 1. The method includes the steps of providing a layer of photosensitive material onto workpiece (wafer) W, projecting an image of the pattern of object (reticle) R through projection optical system PL onto workpiece (wafer) W, and developing the 30 photosensitive material on workpiece (wafer) W. An additional step of forming a predetermined circuit pattern on workpiece (wafer) W (e.g, via an etch process) using the

post-developed photosensitive material as the mask may also be performed. Such a method results in a high-resolution device circuit pattern on workpiece (wafer) W formed substantially without image distortion.

5 With reference now also to FIG. 10 and flow chart 100, a method of manufacturing a semiconductor device is now explained. First, in step 1, a metal film is vapor deposited on each wafer in a "lot" (i.e., group) of wafers. In step 2, photoresist is coated on the metal film on each wafer in the lot. Subsequently, in step 3, using projection exposure apparatus 10 of FIG. 1 provided with a projection optical system PL according to the present invention as 10 described above, the image of the pattern (not shown) on object (reticle) R is sequentially exposed and transferred to one or more exposure fields EF on each wafer W in the lot of wafers, through projection optical system PL. Then, in step 4, the photoresist on each wafer in the lot of wafers is developed. Next, in step 5, by etching each wafer W in the lot of wafers using the developed photoresist as the mask, a circuit pattern corresponding to the 15 pattern on reticle R is formed in each exposure field EF on each wafer W in the lot of wafers. Subsequently, in step 6, by further forming additional circuit patterns (e.g., upper-layer circuit patterns) using the next process, semiconductor devices are manufactured.

Since projection optical system PL in the present example is double-telecentric and its NA is 20 large and variable, fine circuit patterns can be stably formed with high resolution on each wafer W, even if there is warpage in reticle R or warpage in each wafer to be exposed. In addition, since exposure region EF of projection optical system PL is large, large devices can be manufactured with high throughput.

25 Furthermore, it will be understood the present invention is not limited to the abovementioned modes and Working Examples for carrying out the present invention and, within a range that does not deviate from the purport of the present invention, a variety of configurations are obtainable.

What is claimed is:

- 1 1. A projection optical system capable of forming an image of an object, comprising,
2 objectwise to imagewise, along an optical axis:
 - 3 a) a first lens group having positive refractive power;
 - 4 b) a second lens group having negative refractive power;
 - 5 c) a third lens group having positive refractive power;
 - 6 d) a fourth lens group having negative refractive power and a first aspherical
7 surface;
 - 8 e) a fifth lens group having positive refractive power and an aperture stop;
 - 9 f) wherein the projection optical system is designed such that paraxial rays
10 traveling parallel to the optical axis imagewise to objectwise intersect the
11 optical axis at a location Q between said fourth lens group and said fifth lens
12 group;
 - 13 g) at least one of said fourth and fifth lens groups includes a second aspherical
14 surface arranged between said first aspherical and said aperture stop;
 - 15 h) said fifth lens group includes a third aspherical surface arranged imagewise of
16 said aperture stop; and
 - 17 i) wherein the following condition is satisfied:

$$0.01 < d_Q / \{L \times (1 - NA)\} < 0.4 \quad (1)$$

21 wherein the image and the object are separated by a distance L, said location Q
22 and said aperture stop are separated by a distance d_Q , and NA is an imagewise
23 numerical aperture of the projection optical system.

- 1 2. A projection optical system according to claim 1, wherein said aperture stop has a
2 variable size and is located imagewise of said location Q such that vignetting is
3 minimized when said variable size is changed.

1 3. A projection optical system according to claim 1, wherein:

2 a) said first aspherical surface is concave and includes refractive power at a
3 paraxial region and refractive power at a periphery, wherein said refractive
4 power at said periphery is weaker than said refractive power at said paraxial
5 region;

6 b) said second aspherical surface includes refractive power at a paraxial region
7 and refractive power at a periphery, and is one of:

8 i) a convex surface, with said refractive power at said periphery
9 weaker than said refractive power at said paraxial region; and

10 ii) a concave surface, with said refractive power at said periphery
11 stronger than said refractive power at said paraxial region; and

12 c) said third aspherical surface includes refractive power at a paraxial region, and
13 refractive power at a periphery, and is one of:

14 i) a convex surface, with said refractive power at said periphery
15 weaker than said refractive power at said paraxial region; and

16 ii) a concave surface, with said refractive power at said periphery
17 stronger than said refractive power at said paraxial region.

1 4. A projection optical system according to claim 1, wherein said first lens group has at
2 least one aspherical surface.

1 5. A projection optical system according to claim 1, wherein said second lens group has
2 at least one aspherical surface.

1 6. A projection optical system according to claim 1, wherein said third lens group has at
2 least one aspherical surface.

1 7. A projection optical system according to claim 1, satisfying the following conditions:

2

3 $0.05 < f1/L < 0.5$ (2)

4 $0.02 < -f2/L < 0.2$ (3)

$$0.04 < f\beta/L < 0.4 \quad (4)$$

$$0.03 < -f_4/L < 0.3 \quad (5)$$

$$0.04 < f_5/L < 0.4 \quad (6)$$

wherein f1 through f5 are focal lengths of said first through fifth lens groups, respectively.

8. A projection optical system capable of forming an image of an object, comprising, objectwise to imagewise, along an optical axis:

- a) a first lens group having positive refractive power;
- b) a second lens group having negative refractive power;
- c) a third lens group having positive refractive power;
- d) a fourth lens group having negative refractive power and a first aspherical concave surface with refractive power at a paraxial region and refractive power at a periphery, wherein said refractive power at said periphery is weaker than said refractive power at said paraxial region;
- e) a second aspherical surface arranged imagewise of said first aspherical surface and having refractive power at a paraxial region and refractive power at a periphery, and being one of:
 - i) a convex surface, with said refractive power at said periphery weaker than said refractive power at said paraxial region; and
 - ii) a concave surface, with said refractive power at said periphery stronger than said refractive power at paraxial region;
- f) a fifth lens group having positive refractive power, an aperture stop, and a third aspherical surface arranged imagewise of said aperture stop, wherein said third aspherical surface includes a paraxial region, a periphery and refractive power and is one of:
 - i) a convex surface, with said refractive power at said periphery weaker than said refractive power at said paraxial region; and
 - ii) a concave surface, with said refractive power at said periphery stronger than said refractive power at paraxial region; and

25 g) wherein the projection optical system is designed such that paraxial rays
26 traveling parallel to the optical axis imagewise to objectwise intersect the
27 optical axis at a location Q between said fourth lens group and said fifth lens
28 group.

1 9. A projection optical system according to claim 8, wherein said first lens group has at
2 least one aspherical surface.

1 10. A projection optical system according to claim 8, wherein said second lens group has
2 at least one aspherical surface.

1 11. A projection optical system according to claim 8, wherein said third lens group has a
2 least one aspherical surface.

1 12. A projection optical system according to claim 8, satisfying the following conditions:

2

$$3 \quad 0.05 < f1/L < 0.5 \quad (2)$$

4

$$4 \quad 0.02 < -f2/L < 0.2 \quad (3)$$

5

$$5 \quad 0.04 < f3/L < 0.4 \quad (4)$$

6

$$6 \quad 0.03 < -f4/L < 0.3 \quad (5)$$

7

$$7 \quad 0.04 < f5/L < 0.4 \quad (6)$$

8

9 wherein f1 through f5 are focal lengths of said first through fifth lens groups,
10 respectively.

1 13. An exposure apparatus for imaging a pattern present on a reticle onto a photosensitive
2 workpiece, comprising:

3 a) a first stage for supporting the reticle;
4 b) an illumination optical system adjacent said first stage for illuminating the
5 reticle;
6 c) a second stage for supporting a workpiece; and

d) a projection optical system arranged between said first stage and said second stage, said projection optical system comprising in order from said first to said second stage:

- i) a first lens group having positive refractive power;
- ii) a second lens group having negative refractive power;
- iii) a third lens group having positive refractive power;
- iv) a fourth lens group having negative refractive power and a first aspherical surface;
- v) a fifth lens group having positive refractive power and an aperture stop;
- vi) wherein the projection optical system is designed such that paraxial rays traveling parallel to the optical axis imagewise to objectwise intersect the optical axis at a location Q between said fourth lens group and said fifth lens group;
- vii) wherein at least one of said fourth and fifth lens groups includes a second aspherical surface arranged between said first aspherical surface in said fourth lens group and said aperture stop;
- viii) wherein said fifth lens group includes a third aspherical surface arranged imagewise of said aperture stop; and
- ix) wherein the following condition is satisfied:

$$0.01 < d_0 / \{L \times (1 - NA)\} < 0.4 \quad (1)$$

wherein said image and said object are separated by a distance L , said position Q and said aperture stop are separated by a distance d_Q , and NA is an imagewise numerical aperture of the projection optical system.

1 14. An exposure apparatus according to claim 13, wherein said reticle stage and said
2 workpiece stage are moveable along a scanning direction, and said projection optical
3 system includes an exposure field having a first dimension orthogonal to said

4 scanning direction and a second dimension along said scanning direction, wherein
5 said first dimension is greater than said second dimension.

1 15. An exposure apparatus according to claim 14, wherein said first dimension is at least
2 25 mm.

1 16. A method of patterning a photosensitive workpiece with a pattern present on a reticle,
2 the method comprising the steps of:

- 3 a) illuminating the reticle;
- 4 b) projecting light from said reticle with the projection optical system as set forth
5 in claim 1; and
- 6 c) exposing said photosensitive workpiece over an exposure field.

1 17. A device manufacturing method comprising the steps of:

- 2 a) coating a photosensitive material onto a substrate;
- 3 b) projecting onto said substrate the image of a pattern of reticle through the
4 projection optical system set forth in claim 1; and
- 5 c) developing said photosensitive material on said substrate, thereby forming a
6 photoresist pattern.

1 18. A method according to claim 17, further comprising the step, after said step c), of
2 forming a pattern in said substrate based on said photoresist pattern.

1 19. A projection optical system capable of forming an image of an object, comprising,
2 objectwise to imagewise along an optical axis:

- 3 a) a first lens group having positive refractive power and a plurality of lenses
4 including a negative lens;
- 5 b) a second lens group having negative refractive power and a plurality of
6 negative lenses;
- 7 c) a third lens group having positive refractive power and a plurality of positive
8 lenses;

9 d) a fourth lens group having negative refractive power;
10 e) a fifth lens group having positive refractive power and a plurality of lenses
11 including a negative lens; and
12 f) an imagewise maximum numerical aperture NA_{MAX} of at least 0.8.

1 20. A projection optical system according to claim 19, further including an aperture stop
2 located in said fifth lens group.

1 21. A projection optical system according to claim 20, further satisfying the following
2 condition:

3

$$4 \quad 0.01 < d_Q / \{L \times (1 - NA)\} < 0.4 \quad (1)$$

5

6 wherein said image and said object are separated by a distance L, Q is a position
7 located a distance d_Q from said aperture stop wherein paraxial rays traveling parallel
8 to the optical axis imagewise to objectwise intersect the optical axis, and wherein NA
9 is an imagewise numerical aperture of the projection optical system.

1 22. A projection optical system according to claim 20, further including an exposure field
2 having a dimension of at least 25 mm.

1 23. A projection optical system according to claim 20, wherein the number of lenses
2 objectwise of said aperture stop is at least six, and the number of lenses imagewise of
3 said aperture stop is at least four.

1 24. A projection optical system according to claim 20, wherein said aperture stop has a
2 variable size such that the projection optical system has a numerical aperture NA
3 satisfying the relation:

4

$$5 \quad 0.6 \times NA_{MAX} \leq NA \leq NA_{MAX} .$$

1 25. A projection optical system according to claim 20, wherein the optical axis is
2 unfolded.

1 26. A projection optical system having specifications and characteristics as set forth in
2 Tables 1A-1C.

1 27. A projection optical system having specifications and characteristics as set forth in
2 Tables 2A-2C.

1 28. A projection optical system having specifications and characteristics as set forth in
2 Tables 3A-3C.

1 29. A projection optical system having specifications and characteristics as set forth in
2 Tables 4A-4C.

1 30. A projection optical system according to claim 8, satisfying the following conditions:
2
3 $0.05 < f1/L < 0.5$ (2)
4 $0.02 < -f2/L < 0.2$ (3)
5 $0.04 < f3/L < 0.4$ (4)
6 $0.03 < -f4/L < 0.3$ (5)
7 $0.04 < f5/L < 0.4$ (6)
8
9 wherein $f1$ through $f5$ are focal lengths of said first through fifth lens groups,
10 respectively.

1 31. A method of patterning a photosensitive workpiece over an exposure field with a
2 pattern present on a reticle, the method comprising the steps of:
3 a) illuminating the reticle with light;
4 b) projecting the light from the reticle with the projection optical system as set
5 forth in claim 8; and

6 c) exposing the photosensitive workpiece over the exposure field.

1 32. A projection optical system according to claim 1, wherein:

2 (a) said first aspherical surface is concave and includes refractive power at a
3 paraxial region and refractive power at a periphery, wherein said refractive
4 power at said periphery is weaker than said refractive power at said paraxial
5 region;

6 (b) said second aspherical surface including refractive power at a paraxial region,
7 and refractive power at a periphery, wherein said refractive power at said
8 periphery is more negative than said refractive power at said paraxial region;
9 and

10 (c) said third aspherical surface including refractive power at a paraxial region,
11 and refractive power at a periphery, wherein said refractive power at said
12 periphery is more negative than said refractive power at paraxial region.

1 33. An exposure apparatus for imaging a pattern present on a reticle onto a photosensitive
2 workpiece, comprising:

3 (a) a first stage for supporting the reticle;

4 (b) an illumination optical system adjacent said first stage for illuminating the
5 reticle;

6 (c) a second stage for supporting the workpiece; and

7 (d) a projection optical system arranged between said first stage and said second
8 stage, said projection optical system comprising in order from said first to said
9 second stage:

(i) first lens group having positive refractive power;

1 (ii) a second lens group having negative refractive power;

2 (iii) a third lens group having positive refractive power;

13 (iv) a fourth lens group having negative refractive power and a first
14 aspherical concave surface with a paraxial region, a periphery and
15 refractive power, wherein said refractive power at said periphery is
16 weaker than said refractive power at said paraxial region;

17 (v) a second aspherical surface arranged imagewise of said first aspherical
18 surface and having a paraxial region, a periphery and refractive power,
19 said first aspherical surface being one of:
20 (1) a convex surface, with said refractive power at said periphery
21 weaker than said refractive power at said paraxial region; and
22 (2) a concave surface, with said refractive power at said periphery
23 stronger than said refractive power at said paraxial region;
24 (vi) a fifth lens group having positive refractive power, an aperture stop,
25 and a third aspherical surface with a paraxial region, a periphery and
26 refractive power, said third aspherical surface being one of:
27 (1) a convex surface, with said refractive power at said periphery
28 weaker than said refractive power at said paraxial region; and
29 (2) a concave surface, with said refractive power at said periphery
30 stronger than said refractive power at said paraxial region; and
31 (vii) wherein the projection optical system is designed such that paraxial
32 rays traveling parallel to the optical axis imagewise to objectwise
33 intersect the optical axis at a location Q between said fourth lens group
34 and said fifth lens group.

1 34. An exposure apparatus according to claim 33, wherein said first stage and said second
2 stage are movable along a scanning direction, and said projection optical system
3 includes an exposure field having a first dimension orthogonal to said scanning
4 direction, and a second dimension along said scanning direction, wherein said first
5 dimension is greater than second dimension.

1 35. An exposure apparatus for projecting a image of a pattern present on a reticle onto a
2 photosensitive workpiece, comprising:
3 (a) a first stage designed so as to be movable along a scanning direction and to
4 support the reticle;
5 (b) an illuminating optical system adjacent said first stage arranged so as to
6 illuminating the reticle with light;

7 (c) a second stage designed so as to be movable along at least said scanning
8 direction, for supporting the photosensitive workpiece;

9 (d) a projection optical system, arranged between said first stage and said second
10 stage, having a plurality of lenses and an aperture stop, said plurality of lenses
11 and said aperture stop designed such that said light from said reticle is capable
12 of being guided to an exposure field on said substrate with an imagewise
13 maximum numerical aperture of at least 0.8; and

14 (e) wherein said exposure field has a first dimension orthogonal to said scanning
15 direction, and a second dimension along said scanning direction, wherein said
16 first dimension is greater than said second dimension, and wherein said first
17 dimension is at least 15mm.

1 36. A exposure apparatus according to claim 35, wherein said exposure field has a slit
2 shape, with said first dimension of said slit shape being at least 25mm.

1 37. A exposure apparatus according to claim 34, wherein at least one of said plurality of
2 lenses includes an aspherical surface.

1 38. A method of patterning a photosensitive workpiece with a pattern present on a reticle,
2 the method comprising the steps of:
3 (a) illuminating the reticle with light from said illuminating optical system of said
4 exposure apparatus of claim 35;
5 (b) projecting the light from the reticle with the projection optical system of said
6 exposure apparatus of claim 35; and
7 (c) exposing said photosensitive workpiece over said exposure field.

Abstract

A projection optical system (20), exposure apparatus (10) incorporating same, and methods pertaining to same, for manufacturing devices and elements, such as integrated circuits, crystal displays, detectors, MR (magneto-resistive) heads, and the like. The projection

5 optical system comprises a first lens group (G1) having positive refractive power, a second lens group (G2) having negative refractive power, a third lens group (G3) having positive refractive power, a fourth lens group (G4) having negative refractive power and a least a first aspherical surface (ASP1), and a fifth lens group (G5) having positive refractive power and an aperture stop (AS). The projection optical system is designed such that paraxial rays

10 traveling parallel to optical axis (A) imagewise to objectwise intersect the optical axis at a location (Q) between the fourth lens group and the fifth lens group. Further, one of the fourth and fifth lens groups includes at least a second aspherical surface (ASP2) arranged between the first aspherical surface in the fourth lens group and the aperture stop. Also, the fifth lens group includes at least a third aspherical surface (ASP3) arranged imagewise of the aperture

15 stop. The projection optical system also satisfies at least one of a number of design conditions.

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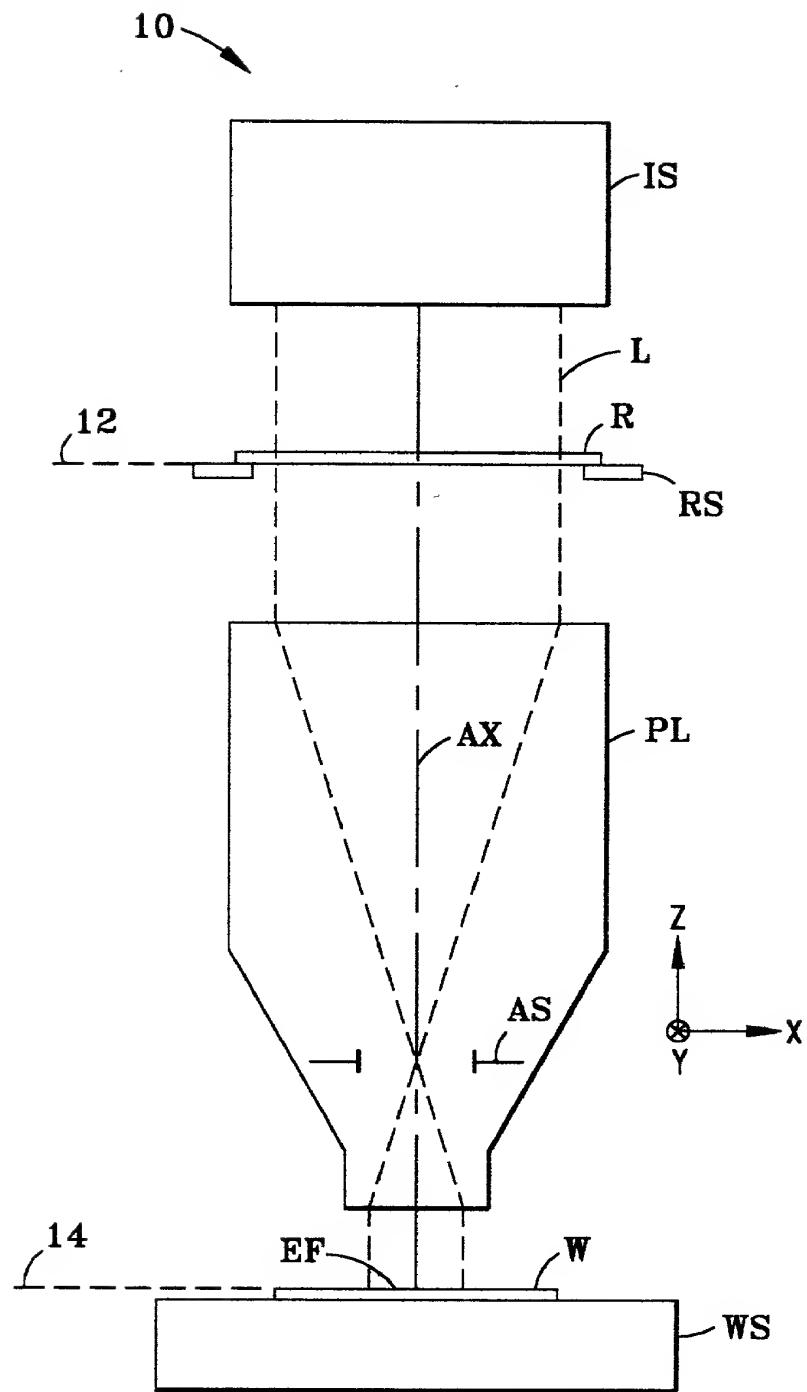


FIG. 1

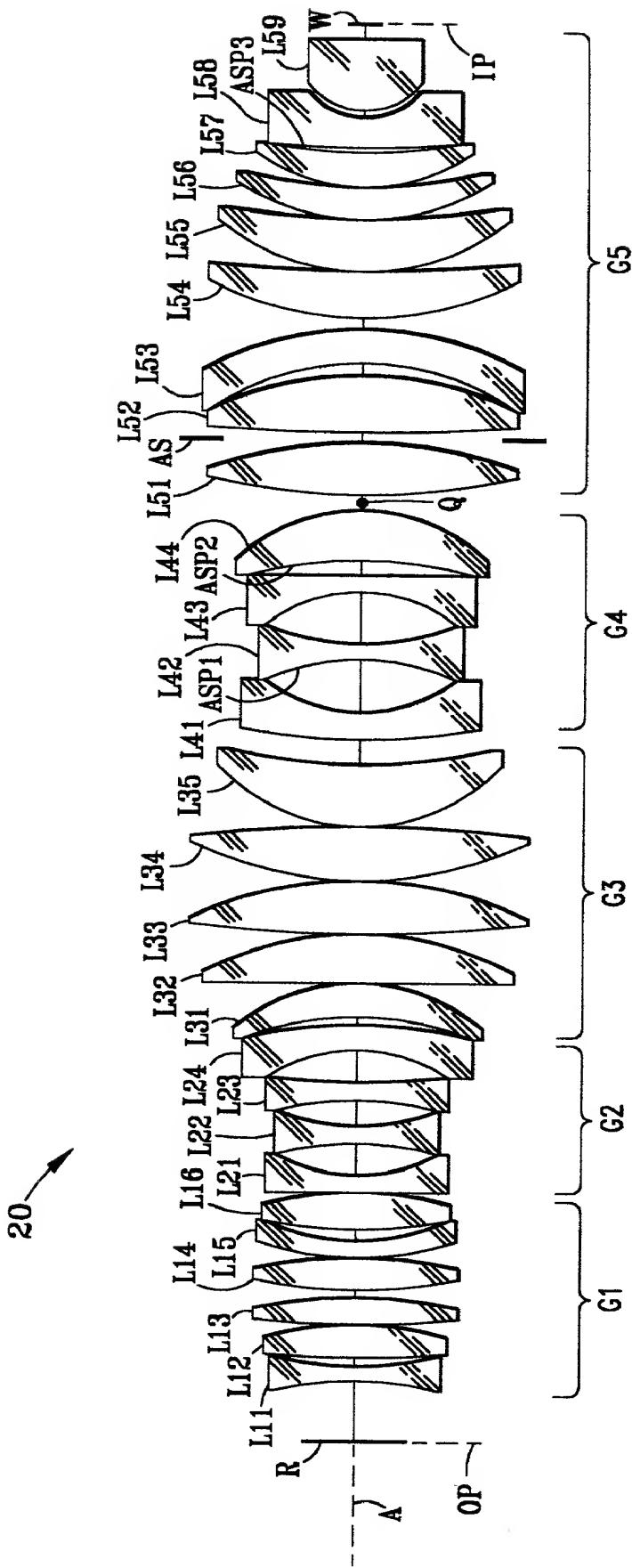


FIG. 2

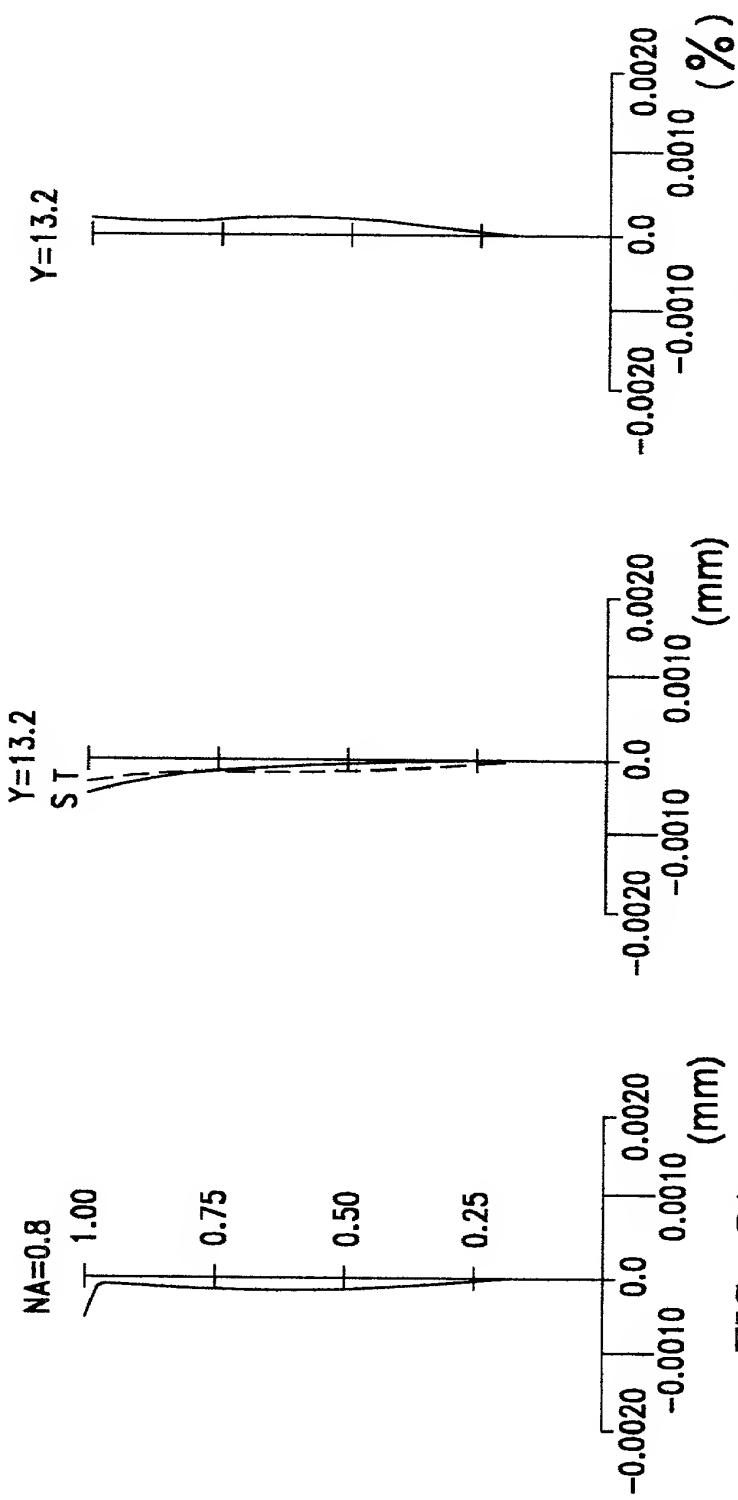


FIG. 3A

FIG. 3B

FIG. 3C

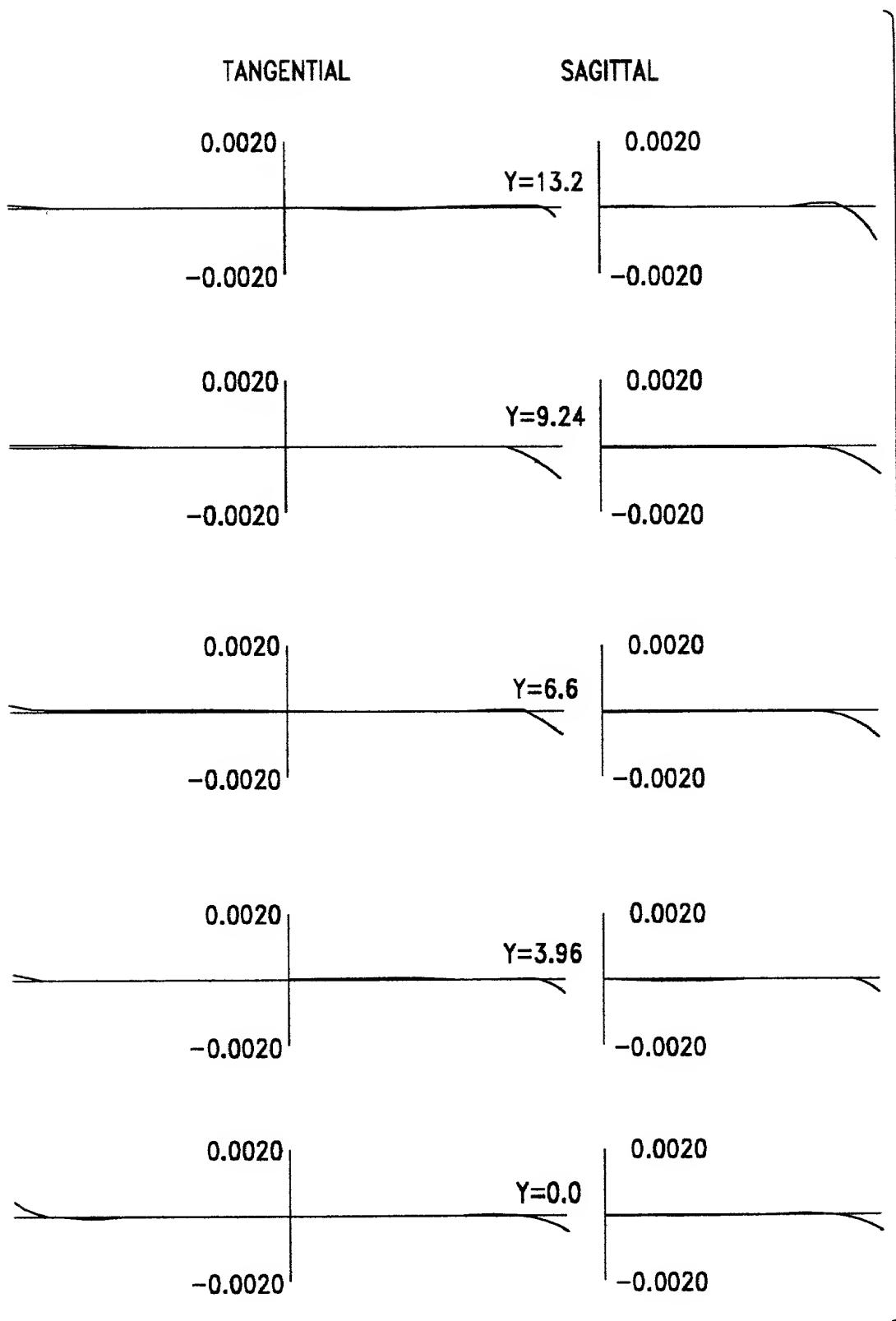


FIG. 3D

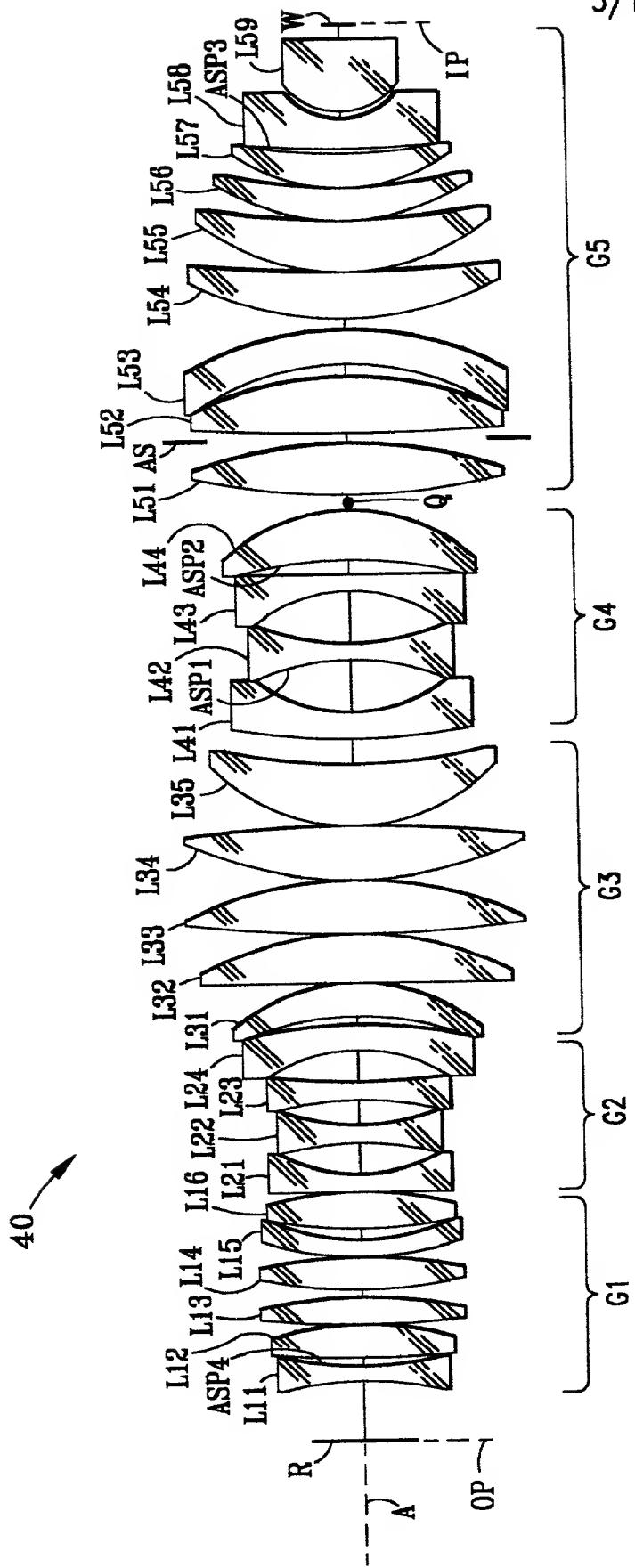
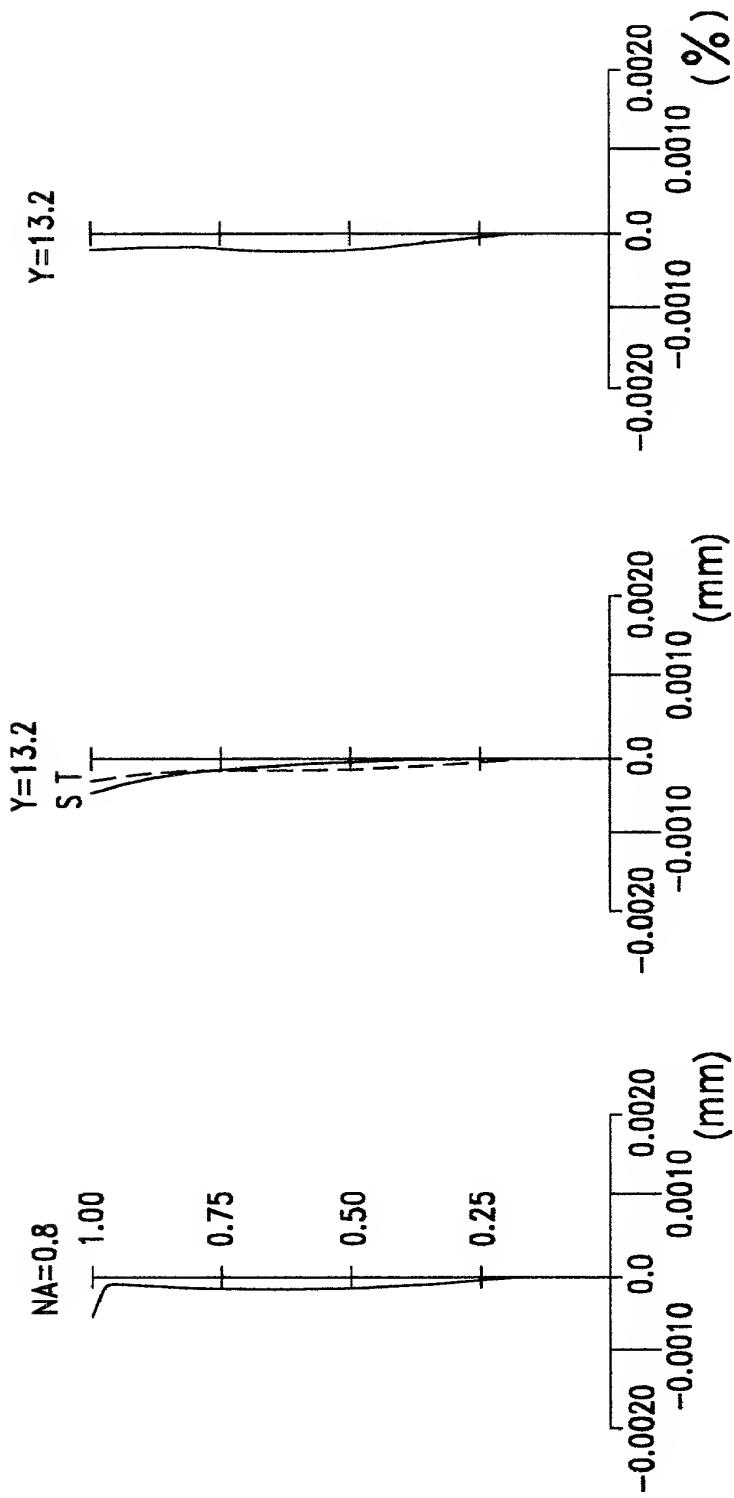


FIG. 4



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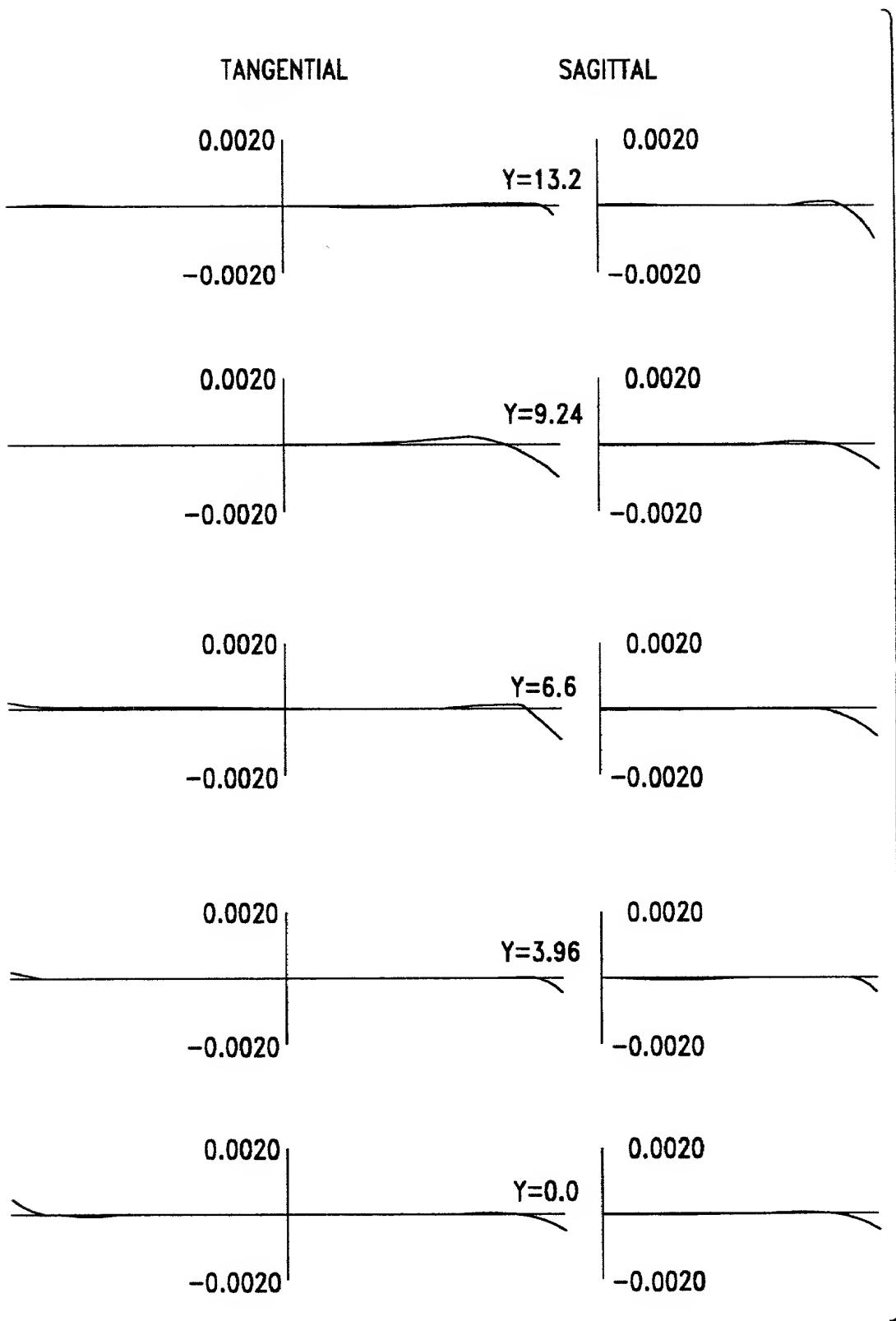


FIG. 5D

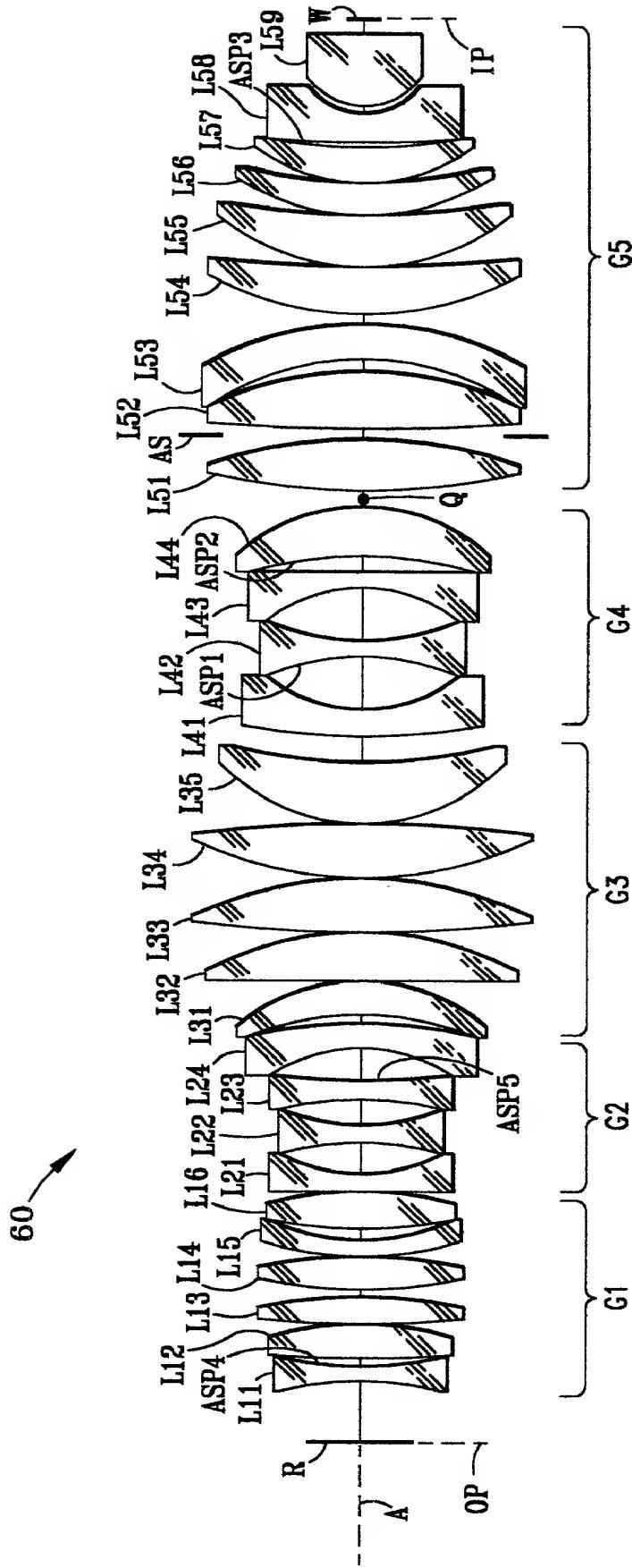


FIG. 6

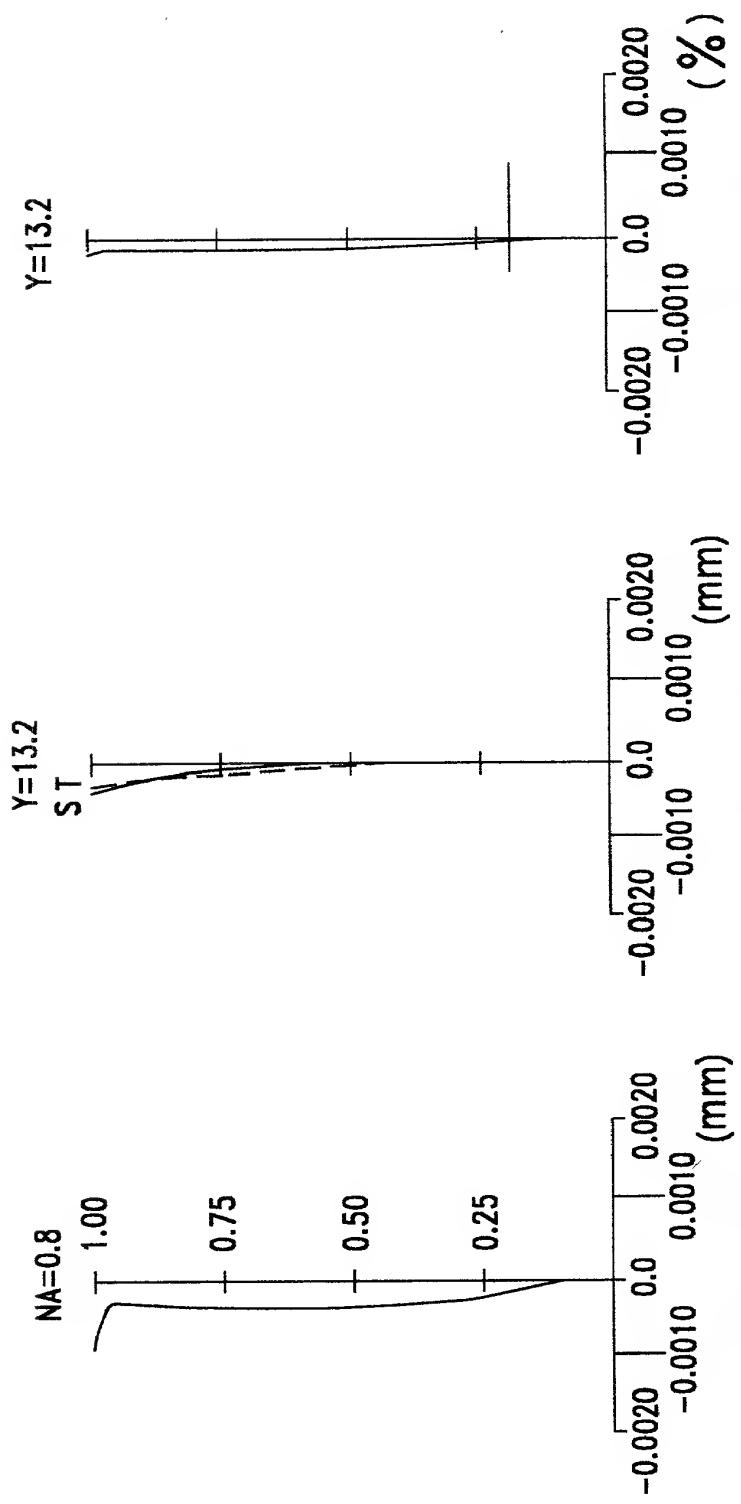


FIG. 7A

FIG. 7B

FIG. 7C

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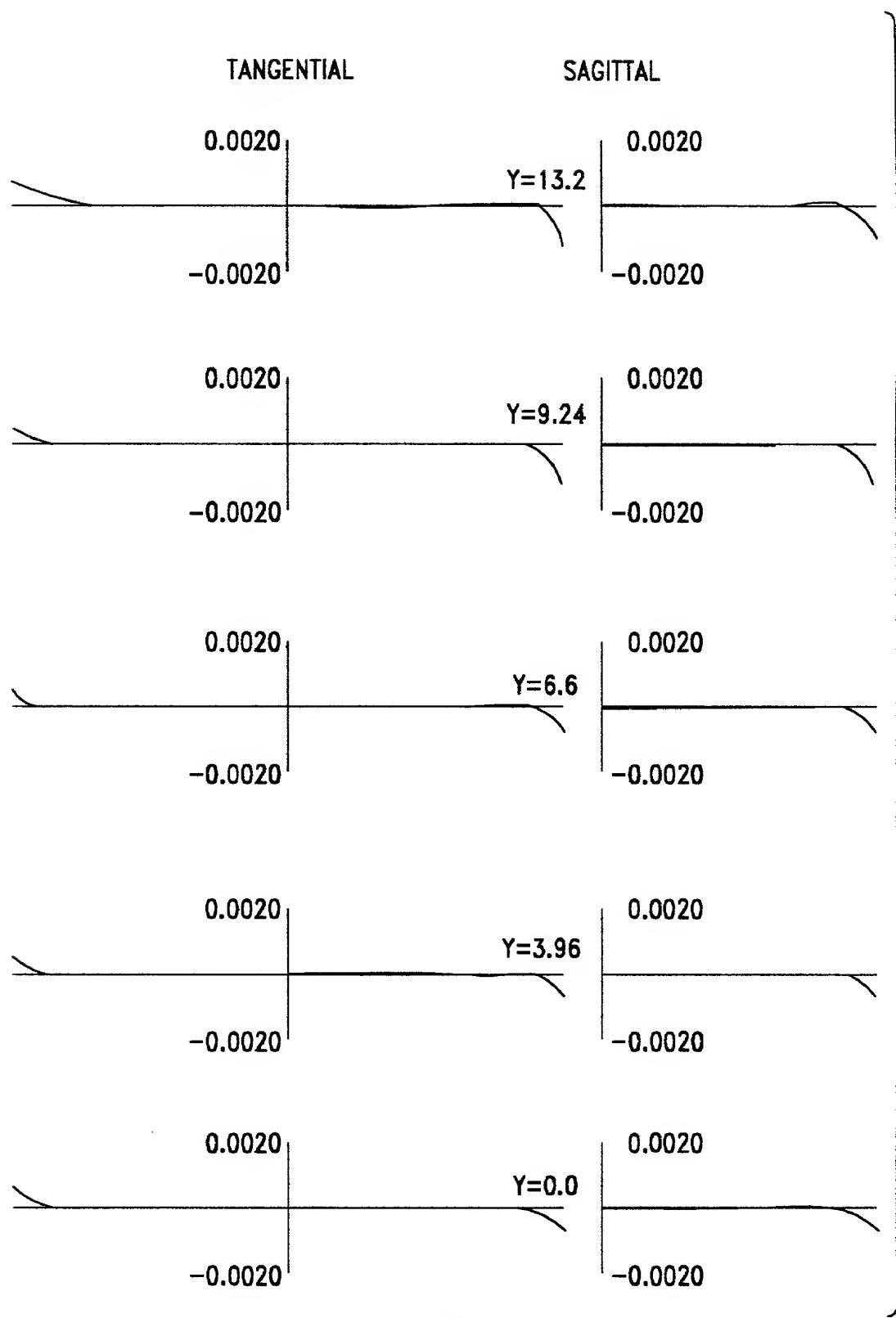


FIG. 7D

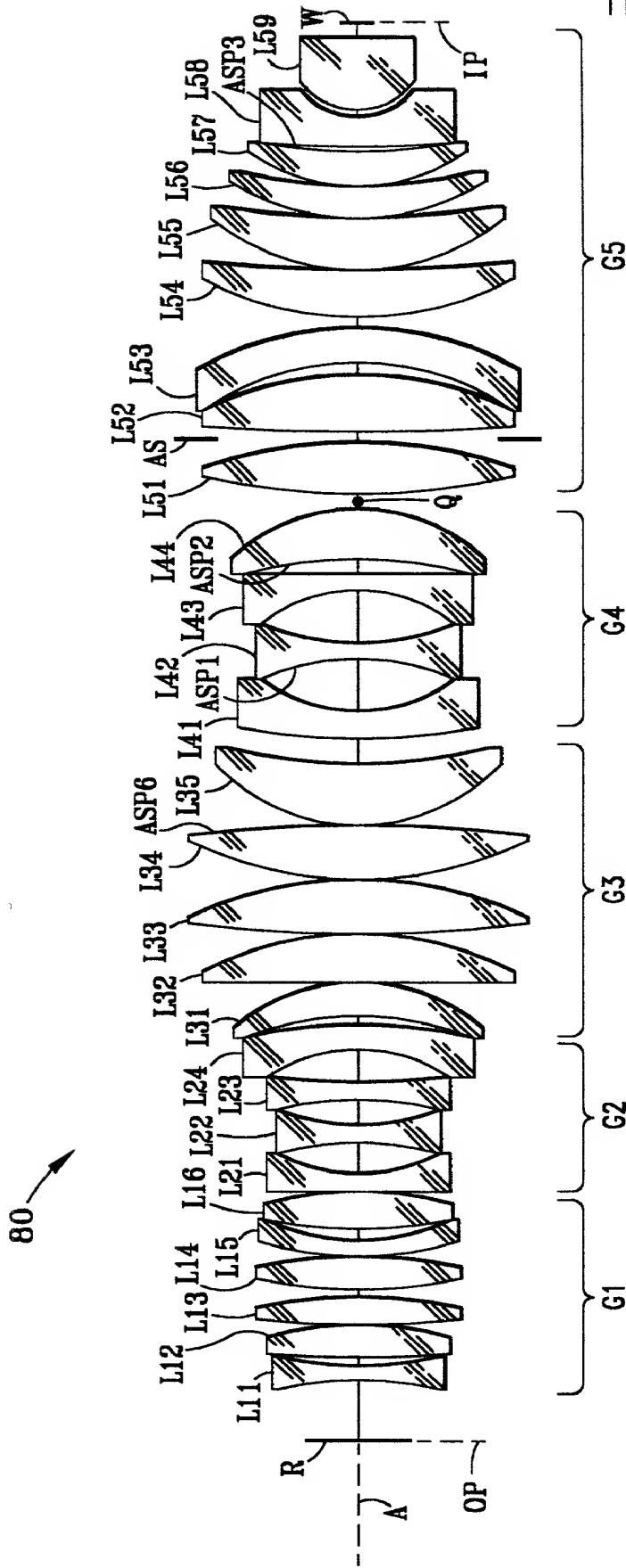
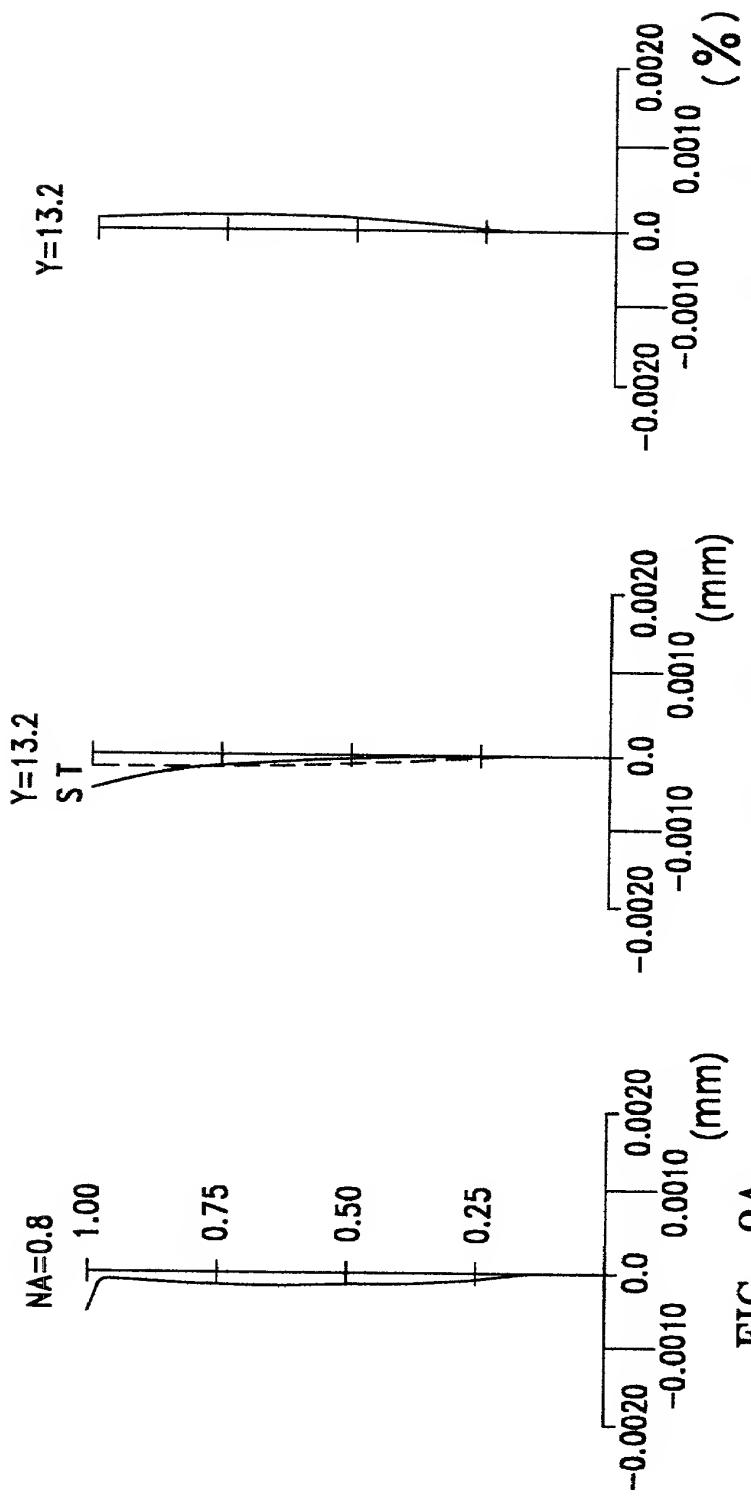


FIG. 8



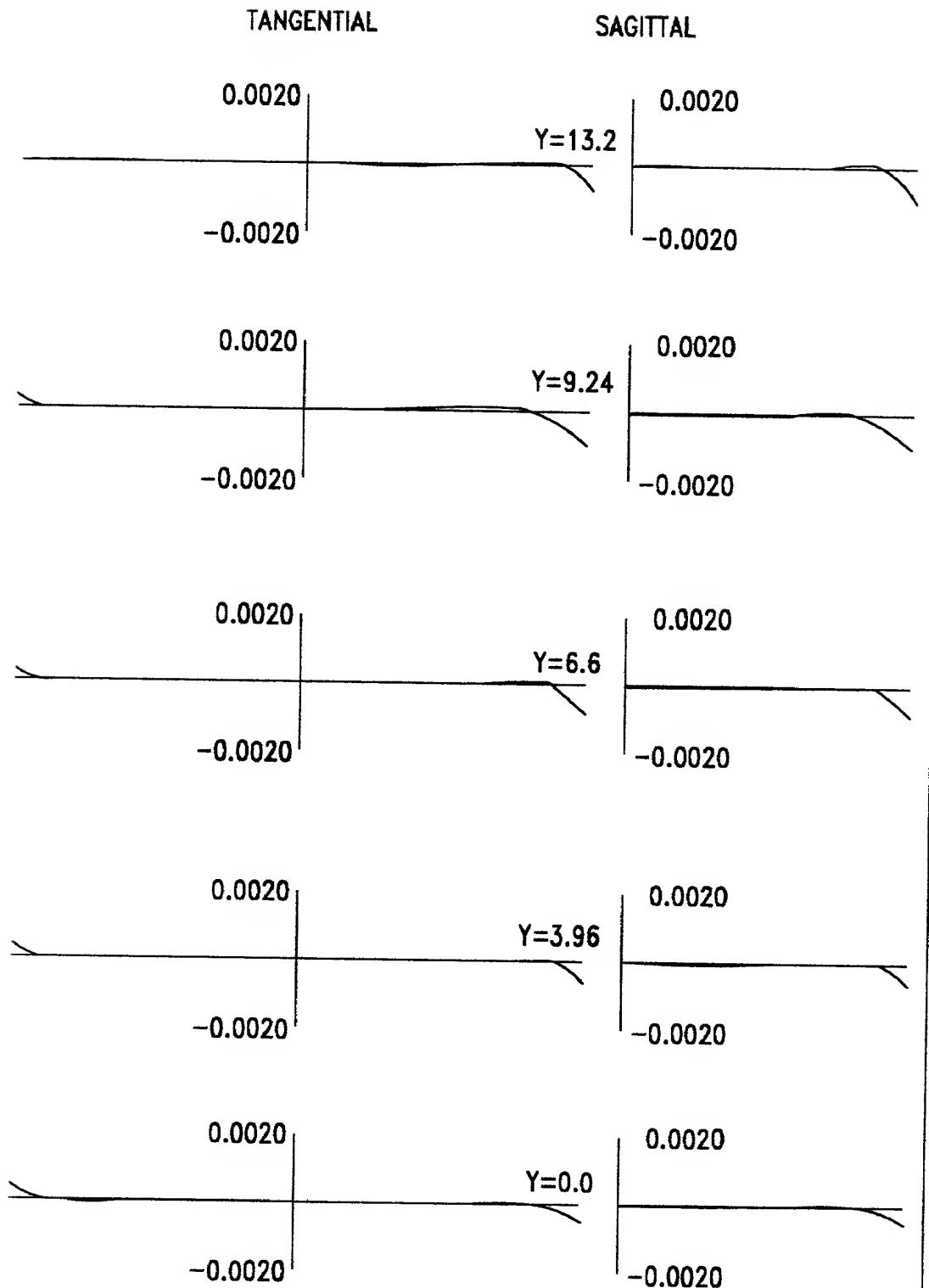


FIG. 9D

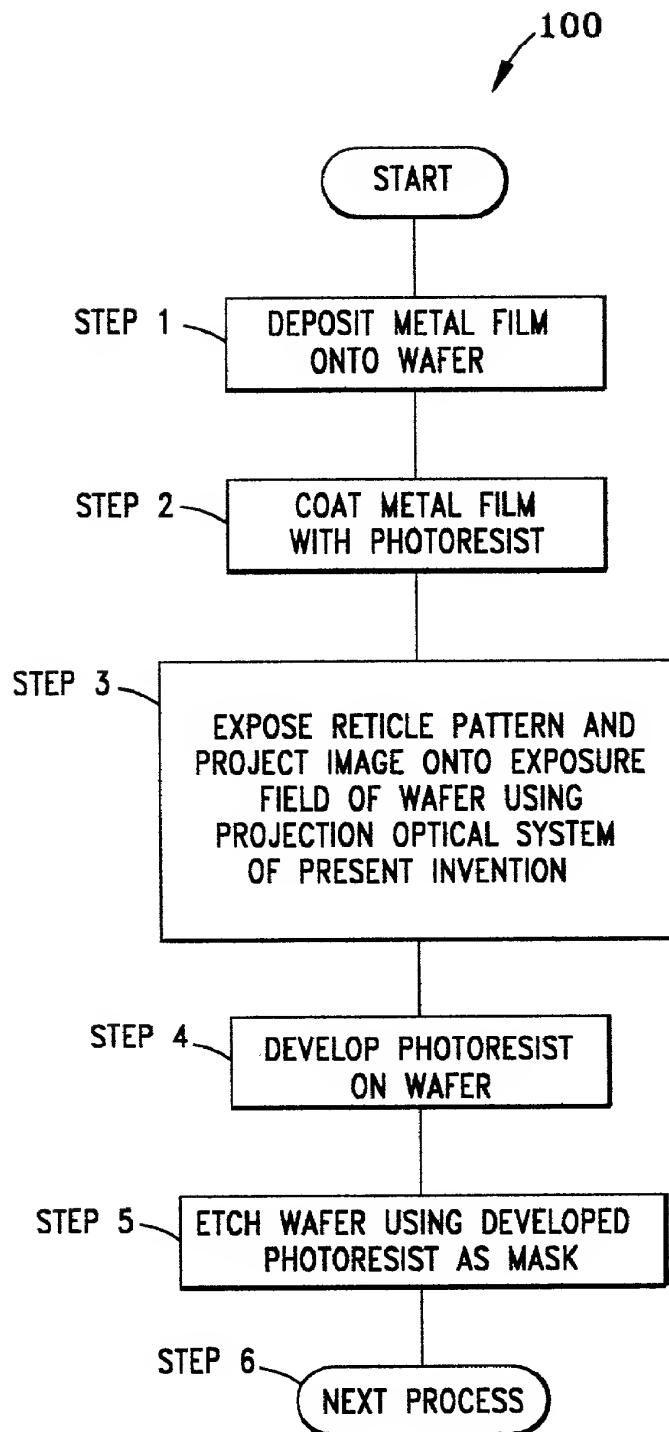


FIG. 10

Declaration and Power of Attorney for Patent Application

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name; I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

**PROJECTION OPTICAL SYSTEM AND EXPOSURE
APPARATUS AND METHOD**

the specification of which (check one)

is attached hereto.

was filed on _____, 1998, as United States Application
Serial No. _____.

I hereby state that I have reviewed and understand the contents of the above- identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information that is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s):

Number	Country	Day/Month/Year	Priority Claimed Yes/No
10-024043	Japan	22/01/1998	Yes
_____	_____	_____	_____
_____	_____	_____	_____

I hereby claim benefit under Title 35, United States Code, §119(e) of any United States provisional applications listed below: NONE.

Provisional Application Number	Filing Date
_____ / _____	_____
_____ / _____	_____

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose information material to the patentability of this application as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Prior U.S. Applications: NONE.

Serial No.	Filing Date	Status (patented, pending, abandoned)
_____	_____	_____
_____	_____	_____

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18

of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

As a named inventor, I hereby appoint the following attorneys and/or agents to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

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BTW115515.I

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Koji SHIGEMATSU

Group Art Unit: 1752

Application No.: 09/234,969

Examiner: Not yet assigned

Filed: January 21, 1999

Docket No.: 105192

For: PROJECTION OPTICAL SYSTEM AND EXPOSURE APPARATUS AND METHOD

POWER OF ATTORNEY BY ASSIGNEE

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

Nikon Corporation, Assignee of the entire right, title and interest in the above patent application by virtue of the Assignment recorded at Reel 9732, Frame 0604 of the Patent Office microfilm records, hereby revokes all prior powers of attorney and appoints the following as attorneys of record with full power of substitution and revocation to prosecute this application and all continuations and divisions thereof, and to transact all business in the Patent and Trademark Office:

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Feb. 23. 2000

Date

Tadao TSURUTA

Signature

Typed Name: Tadao TSURUTA

Title: Executive Vice President